

MB95630H Series

New 8FX 8-bit Microcontrollers

The MB95630H Series is a series of general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers of this series contain a variety of peripheral functions.

Features

- F²MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - Bit test branch instructions
 - Bit manipulation instructions, etc.
- Clock
 - Selectable main clock source
 - Main oscillation clock (up to 16.25 MHz, maximum machine clock frequency: 8.125 MHz)
 - External clock (up to 32.5 MHz, maximum machine clock frequency: 16.25 MHz)
 - Main CR clock (4 MHz ±2%)
 - Main CR PLL clock
 - The main CR PLL clock frequency becomes 8 MHz $\pm 2\%$ when the PLL multiplication rate is 2.
 - The main CR PLL clock frequency becomes 10 MHz
 - $\pm 2\%$ when the PLL multiplication rate is 2.5.
 - The main CR PLL clock frequency becomes 12 MHz \pm 2% when the PLL multiplication rate is 3.
 - $\pm 2\%$ when the PLL multiplication rat
 - The main CR PLL clock frequency becomes 16 MHz $\pm 2\%$ when the PLL multiplication rate is 4.
 - Selectable subclock source
 - Suboscillation clock (32.768 kHz)
 - External clock (32.768 kHz)
 - Sub-CR clock (Typ: 100 kHz, Min: 50 kHz, Max: 150 kHz)
- Timer
 - □ 8/16-bit composite timer × 2 channels
 - □ 8/16-bit PPG × 3 channels
 - □ 16-bit PPG timer × 1 channel (can work independently or together with the multi-pulse generator)
 - 16-bit reload timer × 1 channel (can work independently or together with the multi-pulse generator)
 - Time-base timer × 1 channel
 - \Box Watch prescaler \times 1 channel
- UART/SIO × 1 channel
 - □ Full duplex double buffer
 - Capable of clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer
- I²C bus interface × 1 channel
- Built-in wake-up function
- Multi-pulse generator (MPG) (for DC motor control) × 1 channel
 - 16-bit reload timer × 1 channel
 - 16-bit PPG timer × 1 channel
 - Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function)
- LIN-UART
 - □ Full duplex double buffer

- Capable of clock asynchronous serial data transfer and clock synchronous serial data transfer
- External interrupt × 10 channels
 - Interrupt by edge detection (rising edge, falling edge, and both edges can be selected)
 - Can be used to wake up the device from different low power consumption (standby) modes
- 8/10-bit A/D converter × 8 channels
 - B-bit or 10-bit resolution can be selected.
- Low power consumption (standby) modes
 - There are four standby modes as follows:
 - Stop mode
 - Sleep mode
 - Watch mode
 - Time-base timer mode
 - In standby mode, two further options can be selected: normal standby mode and deep standby mode.
- I/O port
 - □ MB95F632H/F633H/F634H/F636H (number of I/O ports: 28)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 3
 - MB95F632K/F633K/F634K/F636K (number of I/O ports: 29)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 4
- On-chip debug
- 1-wire serial control
- □ Serial writing supported (asynchronous mode)
- Hardware/software watchdog timer
 - Built-in hardware watchdog timer
 - Built-in software watchdog timer
- Power-on reset
 - A power-on reset is generated when the power is switched on.
- Low-voltage detection reset circuit (only available on MB95F632K/F633K/F634K/F636K)
 - Built-in low-voltage detection function (The combination of detection voltage and release voltage can be selected from four options.)
- Comparator
- Clock supervisor counter
- Built-in clock supervisor counter
- Dual operation Flash memory
- The program/erase operation and the read operation can be executed in different banks (upper bank/lower bank) simultaneously.
- Flash memory security function
 - Protects the content of the Flash memory.

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1. Product Line-up

Part number Parameter	MB95F632H	MB95F633H	MB95F634H	MB95F636H	MB95F632K	MB95F633K	MB95F634K	MB95F636K			
Туре				Flash mem	ory product						
Clock supervisor counter	It supervise	upervises the main clock oscillation and the subclock oscillation.									
Flash memory capacity	8 Kbyte	12 Kbyte	20 Kbyte	36 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte	36 Kbyte			
RAM capacity	256 bytes	512 bytes	1024 bytes	1024 bytes	256 bytes	512 bytes	1024 bytes	1024 bytes			
Power-on reset				Ye	es						
Low-voltage detection reset		Ν	0			Y	es				
Reset input		Dedi	cated		S	elected thro	ough softwa	re			
CPU functions	 Instructio Instructio Data bit le Minimum 	Number of basic instructions: 136Instruction bit length: 8 bitsInstruction length: 1 to 3 bytesData bit length: 1, 8 and 16 bitsMinimum instruction execution time: 61.5 ns (machine clock frequency = 16.25 MHz)Interrupt processing time: 0.6 µs (machine clock frequency = 16.25 MHz)									
General-	 I/O port CMOS I/O N-ch ope 	-	: 28 : 25 : 3		 I/O port CMOS I/0 N-ch ope 		: 29 : 25 : 4				
Time-base timer	Interval tim	e: 0.256 ms	to 8.3 s (ex	ternal clock	frequency	= 4 MHz)					
Hardware/ software watchdog timer	Main os		ck at 10 MH	z: 105 ms (l as the sourc	,	ne software	watchdog ti	mer.			
Wild register	It can be us	sed to replace	ce 3 bytes c	of data.							
	 It has a full Both cloc enabled. 	A wide range of communication speed can be selected by a dedicated reload timer. It has a full duplex double buffer. Both clock synchronous serial data transfer and clock asynchronous serial data transfer are									
8/10-bit	8 channels	channels									
A/D converter	8-bit or 10-	-bit or 10-bit resolution can be selected.									
8/16-bit composite timer	 It has the capture for capture for count closes 										



Part number Parameter	MB95F632H	MB95F633H	MB95F634H	MB95F636H	MB95F632K	MB95F633K	MB95F634K	MB95F636K			
External	10 channel	S									
interrupt		nterrupt by edge detection (The rising edge, falling edge, and both edges can be selected.) t can be used to wake up the device from different standby modes.									
()n_chin dahua		1-wire serial control It supports serial writing (asynchronous mode).									
	1 channel										
UART/SIO	 It has a figenerator It uses th LSB-first Both cloce 	Data transfer with UART/SIO is enabled. It has a full duplex double buffer, variable data length (5/6/7/8 bits), an internal baud rate generator and an error detection function. It uses the NRZ type transfer format. LSB-first data transfer and MSB-first data transfer are available to use. Both clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer are enabled.									
	1 channel										
l²C bus interface	 It has the tection full 	 Master/slave transmission and reception It has the following functions: bus error function, arbitration function, transfer direction detection function, wake-up function, and functions of generating and detecting repeated START conditions. 									
	3 channels										
				n "8-bit time be selected				1 channel".			
	1 channel										
timer	The counIt support	iter operatin s external t	g clock can rigger start.	are availab be selected ether with th	l from eight						
	1 channel										
	 Two clock modes and two counter operating modes are available to use. 										
	 16-bit PPG timer: 1 channel 16-bit reload timer operations: toggle output, one-shot output Event counter: 1 channel Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function) 										
Watch prescaler	Eight differe	ent time inte	ervals can b	e selected.							
Comparator	1 channel										





Part number Parameter		MB95F633H	MB95F634H	MB95F	636H	MB95F6	32K	MB95F6	33K	MB95F634k	(MB95F636K			
Flash memory	suspend/It has a flatFlash sector	supports automatic programming (Embedded Algorithm), and program/erase/erase- spend/erase-resume commands.nas a flag indicating the completion of the operation of Embedded Algorithm.ash security feature for protecting the content of the Flash memoryNumber of program/erase cycles100010000												
		r of program tention time	les)00 /ears		0000 years	-	100000 5 years					
Standby mode	 Stop mod Sleep mod Watch mod Time-bas In standby 	here are four standby modes as follows: Stop mode Sleep mode Watch mode Time-base timer mode a standby mode, two further options can be selected: normal standby mode and deep tandby mode.												
Package				DI	P-32	P-M06	FPT-32P-M30 DIP-32P-M06 LCC-32P-M19							

2. Packages And Corresponding Products

Part number Package		MB95F633H	MB95F634H	MB95F636H	MB95F632K	MB95F633K	MB95F634K	MB95F636K
FPT-32P-M30	0	0	0	0	0	0	0	0
DIP-32P-M06	0	0	0	0	0	0	0	0
LCC-32P-M19	0	0	0	0	0	0	0	0

O: Available

3. Differences Among Products And Notes On Product Selection

• Current consumption

When using the on-chip debug function, take account of the current consumption of Flash memory program/erase. For details of current consumption, see "Electrical Characteristics".

Package

For details of information on each package, see "Packages And Corresponding Products" and "Package Dimension".

• Operating voltage

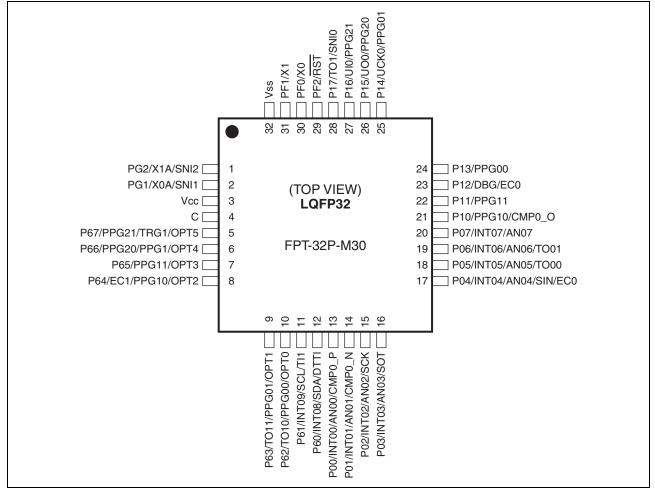
The operating voltage varies, depending on whether the on-chip debug function is used or not. For details of operating voltage, see "Electrical Characteristics".

• On-chip debug function



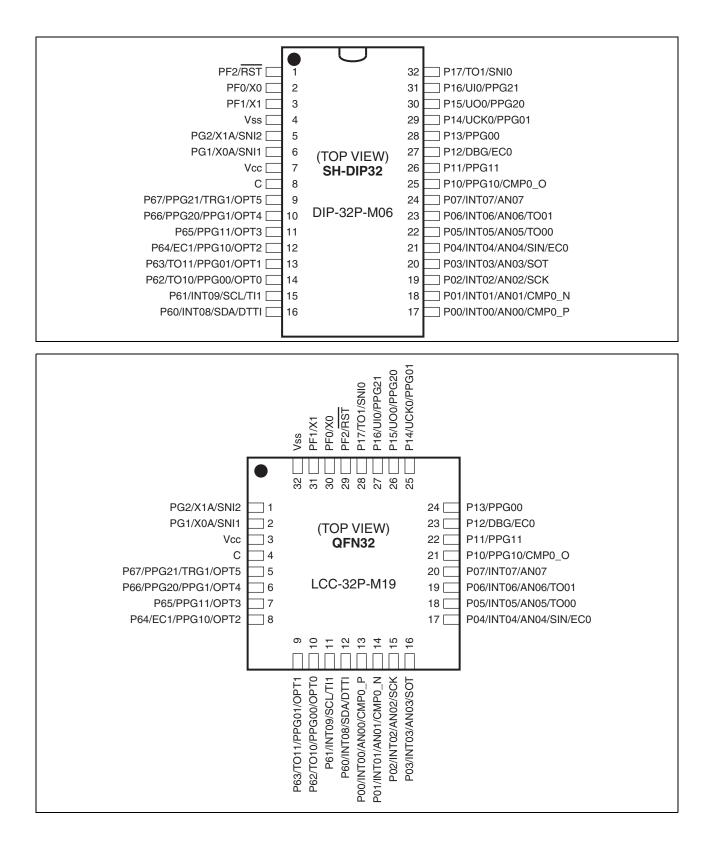
The on-chip debug function requires that Vcc, Vss and one serial wire be connected to an evaluation tool. For details of the connection method, refer to "CHAPTER 25 EXAMPLE OF SERIAL PROGRAMMING CONNECTION" in "New 8FX MB95630H Series Hardware Manual".

4. Pin Assignment











5. Pin Functions

Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*⁵	PU*6
		PG2		General-purpose I/O port				
	_	X1A		Subclock I/O oscillation pin				
1	5	SNI2	С	Trigger input pin for the position detection function of the MPG waveform sequencer	Hysteresis	CMOS		0
		PG1		General-purpose I/O port				
		X0A		Subclock input oscillation pin				
2	6	SNI1	С	Trigger input pin for the position detection function of the MPG waveform sequencer	Hysteresis	CMOS		0
3	7	Vcc	—	Power supply pin	_	—	_	
4	8	С		Decoupling capacitor connection pin				
		P67		General-purpose I/O port High-current pin				
		PPG21		8/16-bit PPG ch. 2 output pin				
5	9	TRG1	D	16-bit PPG timer ch. 1 trigger input pin	Hysteresis	CMOS		0
		OPT5		MPG waveform sequencer output pin				
		P66		General-purpose I/O port High-current pin				
6	10	PPG20	D	8/16-bit PPG ch. 2 output pin	Hysteresis	CMOS		0
0	10	PPG1		16-bit PPG timer ch. 1 output pin	11931616313	CIVICS		0
		OPT4		MPG waveform sequencer output pin				
		P65		General-purpose I/O port High-current pin				
7	11	PPG11	D	8/16-bit PPG ch. 1 output pin	Hysteresis	CMOS		0
		OPT3		MPG waveform sequencer output pin				
		P64		General-purpose I/O port High-current pin				
8	8 12	EC1	D	8/16-bit composite timer ch. 1 clock input pin	Hysteresis	CMOS	_	0
		PPG10		8/16-bit PPG ch. 1 output pin				
		OPT2		MPG waveform sequencer output pin				



Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*5	PU*6
		P63		General-purpose I/O port High-current pin				
9	13	TO11	D	8/16-bit composite timer ch. 1 output pin	Hysteresis	CMOS	_	0
		PPG01		8/16-bit PPG ch. 0 output pin				
		OPT1		MPG waveform sequencer output pin				
		P62		General-purpose I/O port High-current pin				
10	14	TO10	D	8/16-bit composite timer ch. 1 output pin	Hysteresis	CMOS		0
		PPG00		8/16-bit PPG ch. 0 output pin				
		OPT0		MPG waveform sequencer output pin				
		P61		General-purpose I/O port				
		INT09		External interrupt input pin				
11	15	SCL	I	I ² C bus interface ch. 0 clock I/O pin	CMOS	CMOS	0	
		TI1		16-bit reload timer ch. 1 input pin				
		P60 INT08		General-purpose I/O port				
				External interrupt input pin		CMOS	0	
12	16	SDA	I	I²C bus interface ch. 0 data I/O pin	CMOS			—
		DTTI		MPG waveform sequencer input pin				
		P00		General-purpose I/O port				
		INT00		External interrupt input pin				
13	17	AN00	E	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	0
		CMP0_P		Comparator non-inverting analog input (positive input) pin				
		P01		General-purpose I/O port				
		INT01		External interrupt input pin]			
14	14 18	AN01	E	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS		0
				Comparator inverting analog input (negative input) pin				



Pin	Pin no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*⁵	PU*6
		P02		General-purpose I/O port				
		INT02		External interrupt input pin	Hysteresis/			
15	19	AN02 E		8/10-bit A/D converter analog input pin	analog	CMOS		0
		SCK		LIN-UART clock I/O pin				
		P03		General-purpose I/O port				
		INT03		External interrupt input pin	Hysteresis/			
16	20	AN03	E	8/10-bit A/D converter analog input pin	analog	CMOS		0
		SOT		LIN-UART data output pin				
		P04		General-purpose I/O port				
		INT04		External interrupt input pin	-			
17	21	AN04	F	8/10-bit A/D converter analog input pin	CMOS/ analog	CMOS	_	0
		SIN		LIN-UART data input pin	analog			
		EC0		8/16-bit composite timer ch. 0 clock input pin				
		P05		General-purpose I/O port				
		INT05		External interrupt input pin				
18	22	AN05	Е	8/10-bit A/D converter analog input pin	Hysteresis/ analog	СМОЗ	_	0
		TO00		8/16-bit composite timer ch. 0 output pin				
		P06		General-purpose I/O port				
		INT06		External interrupt input pin	-			
19	23	AN06	Е	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	0
		TO01		8/16-bit composite timer ch. 0 output pin				
		P07		General-purpose I/O port				
20	24	INT07	Е	External interrupt input pin	Hysteresis/	CMOS		0
	- •	AN07	_	8/10-bit A/D converter analog input pin	analog			
		P10		General-purpose I/O port				
21	25	PPG10	G	8/16-bit PPG ch. 1 output pin	Hysteresis	CMOS	—	0
				Comparator digital output pin				



$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Pin	no.		I/O			I/O type		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		SH-DIP32*3	Pin name		Function	Input	Output	OD*⁵	PU*6
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	22	26	P11	G	General-purpose I/O port	Hystoresis	CMOS		0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	22	20	PPG11	G	8/16-bit PPG ch. 1 output pin	пузістезіз	CIVICS		0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			P12		General-purpose I/O port				
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	23	27	DBG	н	DBG input pin	Hysteresis	смоз	0	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			EC0					Ū	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	24	20	P13	G	General-purpose I/O port	Hystoresis	CMOS		0
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	24	20	PPG00	G	8/16-bit PPG ch. 0 output pin	пузістезіз	CIVICS		0
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			P14		General-purpose I/O port				
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	25	29	UCK0	G	UART/SIO ch. 0 clock I/O pin	Hysteresis	CMOS		0
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			PPG01		8/16-bit PPG ch. 0 output pin				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			P15		General-purpose I/O port				
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	26	30	UO0	G	UART/SIO ch. 0 data output pin	Hysteresis	CMOS	—	0
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			PPG20		8/16-bit PPG ch. 2 output pin				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			P16		General-purpose I/O port				
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	27	31	UIO	J	UART/SIO ch. 0 data input pin	CMOS	CMOS		0
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			PPG21		8/16-bit PPG ch. 2 output pin				
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			P17		General-purpose I/O port				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	28	32	TO1	G	-	Hysteresis	CMOS		0
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			SNI0	•	detection function of the MPG				Ū
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			PF2		General-purpose I/O port				
30 2 B Image: Constraint of the second secon	29	1	RST	A	Dedicated reset pin on MB95F632H/F633H/F634H/	Hysteresis	CMOS	0	—
X0 Main clock input oscillation pin PF1 General-purpose I/O port	30	n	PF0	P	General-purpose I/O port	Hystorosia	CMOS		
PF1 General-purpose I/O port	30	۷	X0	D	Main clock input oscillation pin	Tysieresis			
A 31 I 3 B B B B B B B B B B B B B B B B B B	31	3	PF1	В	General-purpose I/O port	Hysteresis	CMOS		
X1 Main clock I/O oscillation pin Hysteresis Civics —	51	5	X1	ם	Main clock I/O oscillation pin	1 1931010315	0000		
32 4 Vss — Power supply pin (GND) — P <td>32</td> <td>4</td> <td>Vss</td> <td>_</td> <td>Power supply pin (GND)</td> <td></td> <td></td> <td></td> <td>—</td>	32	4	Vss	_	Power supply pin (GND)				—

O: Available

*1: FPT-32P-M30

*2: LCC-32P-M19

*3: DIP-32P-M06

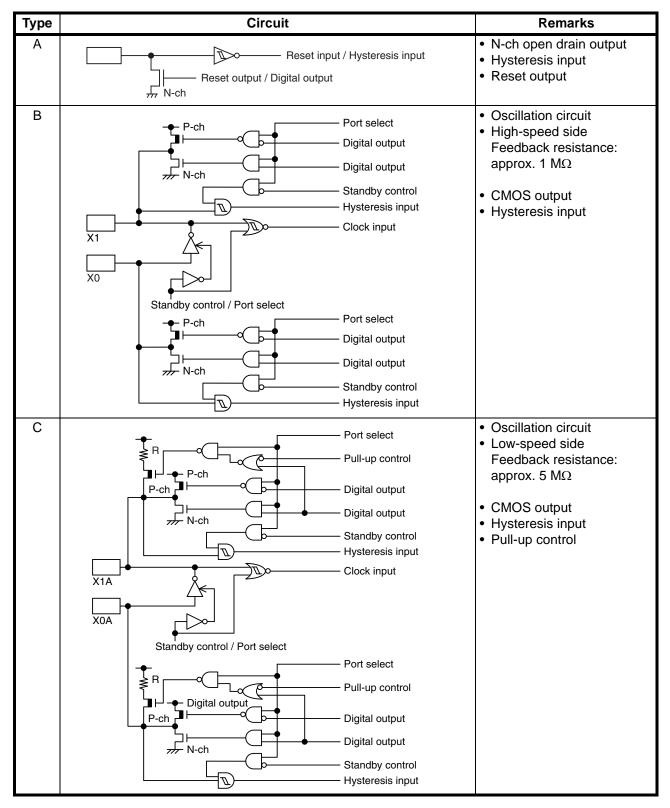
*4: For the I/O circuit types, see "I/O Circuit Type".

*5: N-ch open drain

*6: Pull-up



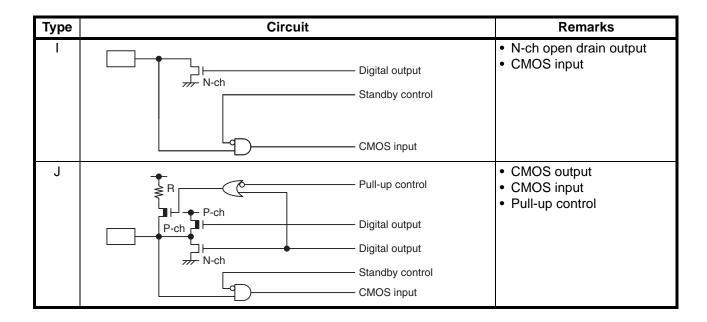
6. I/O Circuit Type





Туре	Circuit		Remarks
D	R C	— Pull-up control	 CMOS output Hysteresis input Pull-up control
	P-ch	— Digital output	High current output
		— Digital output	
		 Standby control Hysteresis input 	
E	R C	— Pull-up control	 CMOS output Hysteresis input Pull-up control
	P-ch	Digital output	Analog input
		— Digital output	
		— Analog input	
		A/D control Standby control Hysteresis input	
F		— Pull-up control	 CMOS output CMOS input Pull-up control
	P-ch	— Digital output	Analog input
		— Digital output	
	▶	— Analog input	
		 A/D control Standby control CMOS input 	
G	R R	— Pull-up control	 CMOS output Hysteresis input Pull-up control
	P-ch P-ch ₽-ch	— Digital output	· · · · · · · · · · · · · · · · · · ·
	<i>with N-ch</i>	Digital output	
		— Hysteresis input	
Н		Standby control Hysteresis input	N-ch open drain outputHysteresis input
	└─── Digital output → N-ch		





7. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

7.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

• Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.



(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.

Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

• Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (2) Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

• Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

7.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

• Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually



causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

• Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

• Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.

When you open Dry Package that recommends humidity 40% to 70% relative humidity.

- (3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

- (1) Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
- (2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 M Ω).

Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.

- (4) Ground all fixtures and instruments, or protect with anti-static measures.
- (5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.





7.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

8. Notes On Device Handling

• Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.

In a CMOS IC, if a voltage higher than Vcc or a voltage lower than Vss is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in "18.1 Absolute Maximum Ratings" of "Electrical Characteristics" is applied to the Vcc pin or the Vss pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

• Stabilizing supply voltage

Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the Vcc power supply voltage.

As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in Vcc ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard Vcc value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

• Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.



9. Pin Connection

• Treatment of unused pins

If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latchups. Always pull up or pull down an unused input pin through a resistor of at least 2 k Ω . Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

• Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the Vcc pin and the Vss pin to the power supply and ground outside the device. In addition, connect the current supply source to the Vcc pin and the Vss pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 μ F as a bypass capacitor between the Vcc pin and the Vss pin at a location close to this device.

• DBG pin

Connect the DBG pin to an external pull-up resistor of 2 k Ω or above.

After power-on, ensure that the DBG pin does not stay at "L" level until the reset output is released.

The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

• RST pin

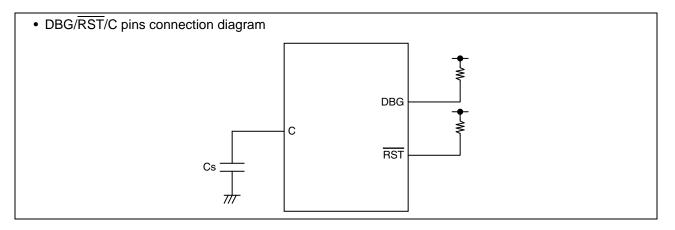
Connect the RST pin to an external pull-up resistor of 2 k $\!\Omega$ or above.

To prevent the device from unintentionally entering the reset mode due to noise, minimize the interconnection length between a pull-up resistor and the \overrightarrow{RST} pin and that between a pull-up resistor and the V_{CC} pin when designing the layout of the printed circuit board.

The PF2/RST pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/RST pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general-purpose I/O function can be selected by the RSTEN bit in the SYSC register.

• C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs. For the connection to a decoupling capacitor Cs, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and Cs and the distance between Cs and the Vss pin when designing the layout of a printed circuit board.



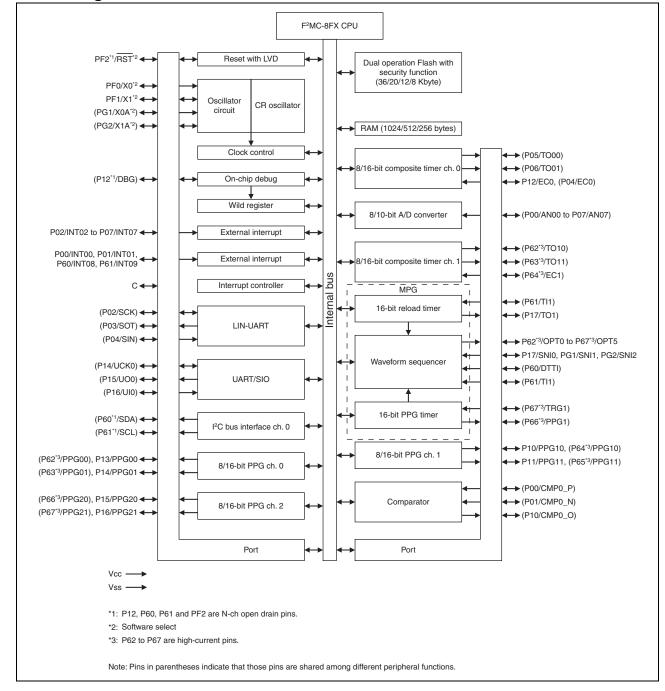
Note on serial communication

In serial communication, reception of wrong data may occur due to noise or other causes. Therefore, design a printed



circuit board to prevent noise from occurring. Taking account of the reception of wrong data, take measures such as adding a checksum to the end of data in order to detect errors. If an error is detected, retransmit the data.

10. Block Diagram



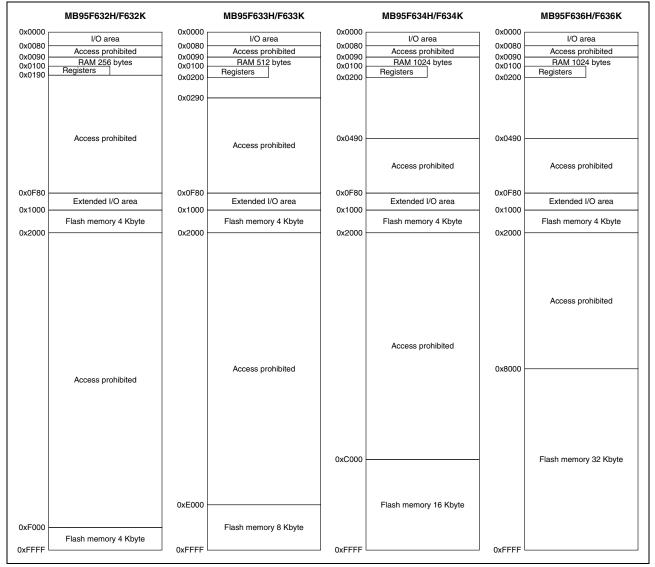


11. CPU Core

• Memory space

The memory space of the MB95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the MB95630H Series are shown below.

• Memory maps





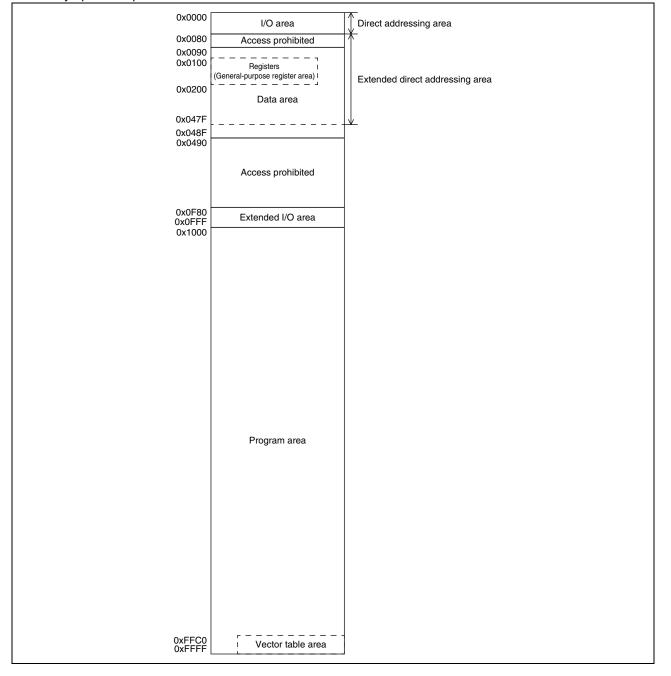
12. Memory Space

The memory space of the MB95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas for specific applications such as general-purpose registers and a vector table.

- I/O area (addresses: 0x0000 to 0x007F)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the I/O area forms part of the memory space, it can be accessed in the same way as the memory. It can also be accessed at high-speed by using direct addressing instructions.
- Extended I/O area (addresses: 0x0F80 to 0x0FFF)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the extended I/O area forms part of the memory space, it can be accessed in the same way as the memory.
- Data area
 - Static RAM is incorporated in the data area as the internal data area.
 - The internal RAM size varies according to product.
 - The RAM area from 0x0090 to 0x00FF can be accessed at high-speed by using direct addressing instructions.
 - In MB95F636H/F636K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In MB95F634H/F634K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In MB95F633H/F633K, the area from 0x0090 to 0x028F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In MB95F632H/F632K, the area from 0x0090 to 0x018F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In MB95F633H/F633K/F634H/F634K/F636H/F636K, the area from 0x0100 to 0x01FF can be used as a generalpurpose register area.
 - In MB95F632H/F632K, the area from 0x0100 to 0x018F can be used as a general-purpose register area.
- Program area
 - The Flash memory is incorporated in the program area as the internal program area.
 - The Flash memory size varies according to product.
 - The area from 0xFFC0 to 0xFFFF is used as the vector table.
 - The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register.



Memory space map





13. Areas For Specific Applications

The general-purpose register area and vector table area are used for the specific applications.

- General-purpose register area (Addresses: 0x0100 to 0x01FF*1)
 - This area contains the auxiliary registers used for 8-bit arithmetic operations, transfer, etc.
 - As this area forms part of the RAM area, it can also be used as conventional RAM.
 - When the area is used as general-purpose registers, general-purpose register addressing enables high-speed access with short instructions.
- Non-volatile register data area (Addresses: 0xFFBB to 0xFFBF)
 - The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register. For details, refer to "CHAPTER 26 NON-VOLATILE REGISTER (NVR) INTERFACE" in "New 8FX MB95630H Series Hardware Manual".
- Vector table area (Addresses: 0xFFC0 to 0xFFFF)
 - This area is used as the vector table for vector call instructions (CALLV), interrupts, and resets.
 - The top of the Flash memory area is allocated to the vector table area. The start address of a service routine is set to an address in the vector table in the form of data.

"Interrupt Source Table" lists the vector table addresses corresponding to vector call instructions, interrupts, and resets.

For details, refer to "CHAPTER 4 RESET", "CHAPTER 5 INTERRUPTS" and "A.2 Special Instruction ■ Special Instruction ● CALLV #vct" in "New 8FX MB95630H Series Hardware Manual".

Direct bank pointer (DP[2:0])	Operand-specified dir	Access area
0bXXX (It does not affect mapping.)	0x0000 to 0x007F	0x0000 to 0x007F
0b000 (Initial value)	0x0090 to 0x00FF	0x0090 to 0x00FF
0b001		0x0100 to 0x017F
0b010		0x0180 to 0x01FF*1
0b011		0x0200 to 0x027F
0b100	0x0080 to 0x00FF	0x0280 to 0x02FF*2
0b101		0x0300 to 0x037F
0b110		0x0380 to 0x03FF
0b111		0x0400 to 0x047F

· Direct bank pointer and access area

*1: Due to the memory size limit, the available access area is up to "0x018F" in MB95F632H/F632K.

*2: Due to the memory size limit, the available access area is up to "0x028F" in MB95F633H/F633K.



14. I/O Map

Address	Register abbreviation	Register name		Initial value
0x0000	PDR0	Port 0 data register		0b0000000
0x0001	DDR0	Port 0 direction register		0b0000000
0x0002	PDR1	Port 1 data register	R/W	0b0000000
0x0003	DDR1	Port 1 direction register	R/W	0b0000000
0x0004	_	(Disabled)	—	—
0x0005	WATR	Oscillation stabilization wait time setting register	R/W	0b11111111
0x0006	PLLC	PLL control register	R/W	0b000X0000
0x0007	SYCC	System clock control register	R/W	0bXXX11011
0x0008	STBC	Standby control register	R/W	0b0000000
0x0009	RSRR	Reset source register	R/W	0b000XXXXX
0x000A	TBTC	Time-base timer control register	R/W	0b0000000
0x000B	WPCR	Watch prescaler control register	R/W	0b00000000
0x000C	WDTC	Watchdog timer control register	R/W	0b00XX0000
0x000D	SYCC2	System clock control register 2	R/W	0bXXXX0011
0x000E	STBC2	Standby control register 2	R/W	0b0000000
0x000F to 0x0015	_	(Disabled)		_
0x0015 0x0016	PDR6	Port 6 data register		0b00000000
0x0010	DDR6	Port 6 direction register		0b00000000
0x0018 to 0x0027	_	(Disabled)		_
0x0028	PDRF	Port F data register		0b0000000
0x0029	DDRF	Port F direction register		0b0000000
0x002A	PDRG	Port G data register		0b00000000
0x002B	DDRG	Port G direction register		0b0000000
0x002C	PUL0	Port 0 pull-up register		0b0000000
0x002D	PUL1	Port 1 pull-up register		0b0000000
0x002E to 0x0032	_	(Disabled)		_
0x0033	PUL6	Port 6 pull-up register		0b00000000
0x0034		(Disabled)		—
0x0035	PULG	Port G pull-up register		0b0000000
0x0036	T01CR1	8/16-bit composite timer 01 status control register 1		0b0000000



Address	Register abbreviation	Register name		Initial value
0x0037	T00CR1	8/16-bit composite timer 00 status control register 1		0b0000000
0x0038	T11CR1	8/16-bit composite timer 11 status control register 1	R/W	0b0000000
0x0039	T10CR1	8/16-bit composite timer 10 status control register 1	R/W	0b0000000
0x003A	PC01	8/16-bit PPG timer 01 control register	R/W	0b0000000
0x003B	PC00	8/16-bit PPG timer 00 control register		0b0000000
0x003C	PC11	8/16-bit PPG timer 11 control register	R/W	0b0000000
0x003D	PC10	8/16-bit PPG timer 10 control register	R/W	0b0000000
0x003E	PC21	8/16-bit PPG timer 21 control register	R/W	0b0000000
0x003F	PC20	8/16-bit PPG timer 20 control register	R/W	0b0000000
0x0040	TMCSRH1	16-bit reload timer control status register (upper)	R/W	0b0000000
0x0041	TMCSRL1	16-bit reload timer control status register (lower)	R/W	0b0000000
0x0042	CMR0C	Comparator control register	R/W	0b00000101
0x0043	_	(Disabled)	—	—
0x0044	PCNTH1	16-bit PPG status control register (upper)	R/W	0b0000000
0x0045	PCNTL1	16-bit PPG status control register (lower)	R/W	0b0000000
0x0046, 0x0047	_	(Disabled)	—	_
0x0048	EIC00	External interrupt circuit control register ch. 0/ch. 1	R/W	0b0000000
0x0049	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	0b0000000
0x004A	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0b0000000
0x004B	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0b0000000
0x004C	EIC01	External interrupt circuit control register ch. 8/ch. 9	R/W	0b0000000
0x004D	_	(Disabled)	—	_
0x004E	LVDR	LVD reset voltage selection ID register	R/W	0b0000000
0x004F		(Disabled)		_
0x0050	SCR	LIN-UART serial control register	R/W	0b0000000
0x0051	SMR	LIN-UART serial mode register	R/W	0b0000000
0x0052	SSR	LIN-UART serial status register		0b00001000
0x0053	RDR	LIN-UART receive data register	R/W	0b00000000
TDR		LIN-UART transmit data register	- K/VV	00000000
0x0054	ESCR	LIN-UART extended status control register		0b00000100
0x0055	ECCR	LIN-UART extended communication control register		0b00000XX
0x0056	SMC10	UART/SIO serial mode control register 1		0b0000000
0x0057	SMC20	UART/SIO serial mode control register 2		0b00100000
0x0058	SSR0	UART/SIO serial status and data register		0b0000001
0x0059	TDR0	UART/SIO serial output data register		0b0000000



Address	Register abbreviation	Register name		Initial value
0x005A	RDR0	UART/SIO serial input data register		0b0000000
0x005B to 0x005F	_	(Disabled)		—
0x0060	IBCR00	I ² C bus control register 0 ch. 0	R/W	0b0000000
0x0061	IBCR10	I ² C bus control register 1 ch. 0	R/W	0b0000000
0x0062	IBSR0	I ² C bus status register ch. 0	R/W	0b0000000
0x0063	IDDR0	I ² C data register ch. 0	R/W	0b0000000
0x0064	IAAR0	I ² C address register ch. 0	R/W	0b0000000
0x0065	ICCR0	I ² C clock control register ch. 0	R/W	0b0000000
0x0066	OPCUR	16-bit MPG output control register (upper)	R/W	0b0000000
0x0067	OPCLR	16-bit MPG output control register (lower)	R/W	0b0000000
0x0068	IPCUR	16-bit MPG input control register (upper)	R/W	0b0000000
0x0069	IPCLR	16-bit MPG input control register (lower)	R/W	0b0000000
0x006A	NCCR	16-bit MPG noise cancellation control register	R/W	0b0000000
0x006B	TCSR	16-bit MPG timer control status register	R/W	0b0000000
0x006C	ADC1	8/10-bit A/D converter control register 1	R/W	0b0000000
0x006D	ADC2	8/10-bit A/D converter control register 2	R/W	0b0000000
0x006E	ADDH	8/10-bit A/D converter data register (upper)	R/W	0b0000000
0x006F	ADDL	8/10-bit A/D converter data register (lower)		0b0000000
0x0070	_	(Disabled)	—	—
0x0071	FSR2	Flash memory status register 2	R/W	0b0000000
0x0072	FSR	Flash memory status register	R/W	0b000X0000
0x0073	SWRE0	Flash memory sector write control register 0	R/W	0b0000000
0x0074	FSR3	Flash memory status register 3	R	0b000XXXXX
0x0075	FSR4	Flash memory status register 4	R/W	0b0000000
0x0076	WREN	Wild register address compare enable register	R/W	0b0000000
0x0077	WROR	Wild register data test setting register	R/W	0b0000000
0x0078	—	Mirror of register bank pointer (RP) and direct bank pointer (DP)		_
0x0079	ILR0	Interrupt level setting register 0		0b11111111
0x007A	ILR1	Interrupt level setting register 1		0b11111111
0x007B	ILR2	Interrupt level setting register 2		0b11111111
0x007C	ILR3	Interrupt level setting register 3		0b11111111
0x007D	ILR4	Interrupt level setting register 4		0b11111111
0x007E	ILR5	Interrupt level setting register 5		0b11111111
0x007F		(Disabled)		



Address	Register abbreviation	Register name		Initial value
0x0F80	WRARH0	Wild register address setting register (upper) ch. 0		0b0000000
0x0F81	WRARL0	Wild register address setting register (lower) ch. 0		0b0000000
0x0F82	WRDR0	Wild register data setting register ch. 0		0b0000000
0x0F83	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0b0000000
0x0F84	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0b0000000
0x0F85	WRDR1	Wild register data setting register ch. 1	R/W	0b0000000
0x0F86	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0b0000000
0x0F87	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0b0000000
0x0F88	WRDR2	Wild register data setting register ch. 2	R/W	0b0000000
0x0F89 to 0x0F91	_	(Disabled)	_	_
0x0F92	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0b0000000
0x0F93	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0b0000000
0x0F94	T01DR	8/16-bit composite timer 01 data register	R/W	0b0000000
0x0F95	T00DR	8/16-bit composite timer 00 data register	R/W	0b0000000
0x0F96	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0b00000000
0x0F97	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	0b0000000
0x0F98	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	0b0000000
0x0F99	T11DR	8/16-bit composite timer 11 data register	R/W	0b0000000
0x0F9A	T10DR	8/16-bit composite timer 10 data register		0b0000000
0x0F9B	TMCR1	8/16-bit composite timer 10/11 timer mode control register		0b00000000
0x0F9C	PPS01	8/16-bit PPG01 cycle setting buffer register	R/W	0b11111111
0x0F9D	PPS00	8/16-bit PPG00 cycle setting buffer register	R/W	0b11111111
0x0F9E	PDS01	8/16-bit PPG01 duty setting buffer register	R/W	0b11111111
0x0F9F	PDS00	8/16-bit PPG00 duty setting buffer register	R/W	0b11111111
0x0FA0	PPS11	8/16-bit PPG11 cycle setting buffer register		0b11111111
0x0FA1	PPS10	8/16-bit PPG10 cycle setting buffer register		0b11111111
0x0FA2	PDS11	8/16-bit PPG11 duty setting buffer register		0b11111111
0x0FA3	PDS10	8/16-bit PPG10 duty setting buffer register		0b11111111
0x0FA4	PPGS	8/16-bit PPG start register		0b0000000
0x0FA5	REVC	8/16-bit PPG output inversion register		0b0000000
0x0FA6	PPS21	8/16-bit PPG21 cycle setting buffer register		0b11111111
0x0FA7	PPS20	8/16-bit PPG20 cycle setting buffer register		0b11111111



Address	Register abbreviation	Register name		Initial value
0x0FA8	TMRH1	16-bit reload timer timer register (upper)	R/W	0b00000000
UXUFAO	TMRLRH1	16-bit reload timer reload register (upper)		0000000000
0x0FA9	TMRL1			050000000
UXUFA9	TMRLRL1			0b00000000
0x0FAA	PDS21	8/16-bit PPG21 duty setting buffer register	R/W	0b11111111
0x0FAB	PDS20	8/16-bit PPG20 duty setting buffer register	R/W	0b11111111
0x0FAC to 0x0FAF	_	(Disabled)	_	_
0x0FB0	PDCRH1	16-bit PPG downcounter register (upper)	R	0b0000000
0x0FB1	PDCRL1	16-bit PPG downcounter register (lower)	R	0b0000000
0x0FB2	PCSRH1	16-bit PPG cycle setting buffer register (upper)	R/W	0b11111111
0x0FB3	PCSRL1	16-bit PPG cycle setting buffer register (lower)	R/W	0b11111111
0x0FB4	PDUTH1	16-bit PPG duty setting buffer register (upper)	R/W	0b11111111
0x0FB5	PDUTL1	16-bit PPG duty setting buffer register (lower)	R/W	0b11111111
0x0FB6 to 0x0FBB	—	(Disabled)		—
0x0FBC	BGR1	LIN-UART baud rate generator register 1	R/W	0b0000000
0x0FBD	BGR0	LIN-UART baud rate generator register 0		0b0000000
0x0FBE	PSSR0	UART/SIO dedicated baud rate generator prescaler select register		0b00000000
0x0FBF	BRSR0	UART/SIO dedicated baud rate generator baud rate setting register		0b00000000
0x0FC0 to 0x0FC2	_	(Disabled)		_
0x0FC3	AIDRL	A/D input disable register (lower)	R/W	0b0000000
0x0FC4	OPDBRH0	16-bit MPG output data buffer register (upper) ch. 0	R/W	0b0000000
0x0FC5	OPDBRL0	16-bit MPG output data buffer register (lower) ch. 0	R/W	0b0000000
0x0FC6	OPDBRH1	16-bit MPG output data buffer register (upper) ch. 1		0b0000000
0x0FC7	OPDBRL1	16-bit MPG output data buffer register (lower) ch. 1		0b0000000
0x0FC8	OPDBRH2	16-bit MPG output data buffer register (upper) ch. 2		0b0000000
0x0FC9	OPDBRL2	16-bit MPG output data buffer register (lower) ch. 2		0b0000000
0x0FCA	OPDBRH3	16-bit MPG output data buffer register (upper) ch. 3		0b0000000
0x0FCB	OPDBRL3	16-bit MPG output data buffer register (lower) ch. 3		0b0000000
0x0FCC	OPDBRH4	16-bit MPG output data buffer register (upper) ch. 4		0b0000000
0x0FCD	OPDBRL4	16-bit MPG output data buffer register (lower) ch. 4	R/W	0b0000000



Address	Register abbreviation	Register name		Initial value
0x0FCE	OPDBRH5	16-bit MPG output data buffer register (upper) ch. 5		0b0000000
0x0FCF	OPDBRL5	16-bit MPG output data buffer register (lower) ch. 5		0b0000000
0x0FD0	OPDBRH6	16-bit MPG output data buffer register (upper) ch. 6		0b0000000
0x0FD1	OPDBRL6	16-bit MPG output data buffer register (lower) ch. 6	R/W	0b0000000
0x0FD2	OPDBRH7	16-bit MPG output data buffer register (upper) ch. 7		0b0000000
0x0FD3	OPDBRL7	16-bit MPG output data buffer register (lower) ch. 7	R/W	0b0000000
0x0FD4	OPDBRH8	16-bit MPG output data buffer register (upper) ch. 8	R/W	0b0000000
0x0FD5	OPDBRL8	16-bit MPG output data buffer register (lower) ch. 8	R/W	0b0000000
0x0FD6	OPDBRH9	16-bit MPG output data buffer register (upper) ch. 9	R/W	0b0000000
0x0FD7	OPDBRL9	16-bit MPG output data buffer register (lower) ch. 9	R/W	0b0000000
0x0FD8	OPDBRHA	16-bit MPG output data buffer register (upper) ch. A	R/W	0b0000000
0x0FD9	OPDBRLA	16-bit MPG output data buffer register (lower) ch. A	R/W	0b0000000
0x0FDA	OPDBRHB	16-bit MPG output data buffer register (upper) ch. B	R/W	0b0000000
0x0FDB	OPDBRLB	16-bit MPG output data buffer register (lower) ch. B	R/W	0b0000000
0x0FDC	OPDUR	16-bit MPG output data register (upper)	R	0b0000XXXX
0x0FDD	OPDLR	16-bit MPG output data register (lower)	R	0bXXXXXXXX
0x0FDE	CPCUR	16-bit MPG compare clear register (upper)	R/W	0bXXXXXXXX
0x0FDF	CPCLR	16-bit MPG compare clear register (lower)		0bXXXXXXXX
0x0FE0, 0x0FE1	_	(Disabled)		_
0x0FE2	TMBUR	16-bit MPG timer buffer register (upper)		0bXXXXXXXX
0x0FE3	TMBLR	16-bit MPG timer buffer register (lower)	R	0bXXXXXXXX
0x0FE4	CRTH	Main CR clock trimming register (upper)	R/W	0b000XXXXX
0x0FE5	CRTL	Main CR clock trimming register (lower)	R/W	0b000XXXXX
0x0FE6		(Disabled)		—
0x0FE7	CRTDA	Main CR clock temperature dependent adjustment register	R/W	0b000XXXXX
0x0FE8	SYSC	System configuration register		0b11000011
0x0FE9	CMCR	Clock monitoring control register		0b0000000
0x0FEA	CMDR	Clock monitoring data register		0b0000000
0x0FEB	WDTH	Watchdog timer selection ID register (upper)		0bXXXXXXXX
0x0FEC	WDTL	Watchdog timer selection ID register (lower)		0bXXXXXXXX
0x0FED, 0x0FEE	_	(Disabled)		_
0x0FEF	WICR	Interrupt pin selection circuit control register		0b01000000
0x0FF0 to 0x0FFF	_	(Disabled)		_



- R/W access symbols
 - R/W : Readable/Writable
 - R : Read only
- Initial value symbols
 - 0 : The initial value of this bit is "0".
 - 1 : The initial value of this bit is "1".
 - X : The initial value of this bit is undefined.

Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.

15. I/O Ports

· List of port registers

Register name	Read/Write	Initial value	
Port 0 data register	PDR0	R, RM/W	0b0000000
Port 0 direction register	DDR0	R/W	0b0000000
Port 1 data register	PDR1	R, RM/W	0b0000000
Port 1 direction register	DDR1	R/W	0b0000000
Port 6 data register	PDR6	R, RM/W	0b0000000
Port 6 direction register	DDR6	R/W	0b0000000
Port F data register	PDRF	R, RM/W	0b0000000
Port F direction register	DDRF	R/W	0b0000000
Port G data register	PDRG	R, RM/W	0b0000000
Port G direction register	DDRG	R/W	0b0000000
Port 0 pull-up register	PUL0	R/W	0b0000000
Port 1 pull-up register	PUL1	R/W	0b0000000
Port 6 pull-up register	PUL6	R/W	0b0000000
Port G pull-up register	PULG	R/W	0b0000000
A/D input disable register (lower)	AIDRL	R/W	0b0000000

R/W : Readable/writable (The read value is the same as the write value.)

R, RM/W : Readable/writable (The read value is different from the write value. The write value is read by the readmodify-write (RMW) type of instruction.)



15.1 Port 0

Port 0 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.1.1 Port 0 configuration

- Port 0 is made up of the following elements.
- General-purpose I/O pins/peripheral function I/O pins
- Port 0 data register (PDR0)
- Port 0 direction register (DDR0)
- Port 0 pull-up register (PUL0)
- A/D input disable register (lower) (AIDRL)

15.1.2 Block diagrams of port 0

- P00/INT00/AŇ00/CMP0_P pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT00)
 - 8/10-bit A/D converter analog input pin (AN00)
 - Comparator non-inverting analog input (positive input) pin (CMP0_P)

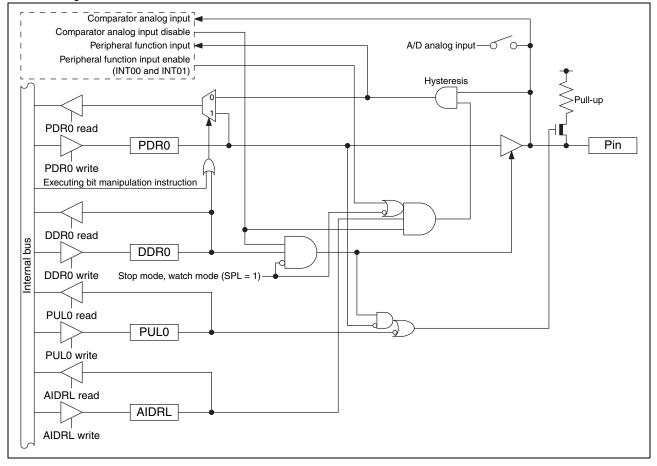
• P01/INT01/AN01/CMP0_N pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT01)
- 8/10-bit A/D converter analog input pin (AN01)
- Comparator inverting analog input (negative input) pin (CMP0_N)



Block diagram of P00/INT00/AN00/CMP0_P and P01/INT01/AN01/CMP0_N







P02/INT02/AN02/SCK pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT02)
- 8/10-bit A/D converter analog input pin (AN02)
- LIN-UART clock I/O pin (SCK)

• P03/INT03/AN03/SOT pin

This pin has the following peripheral functions:

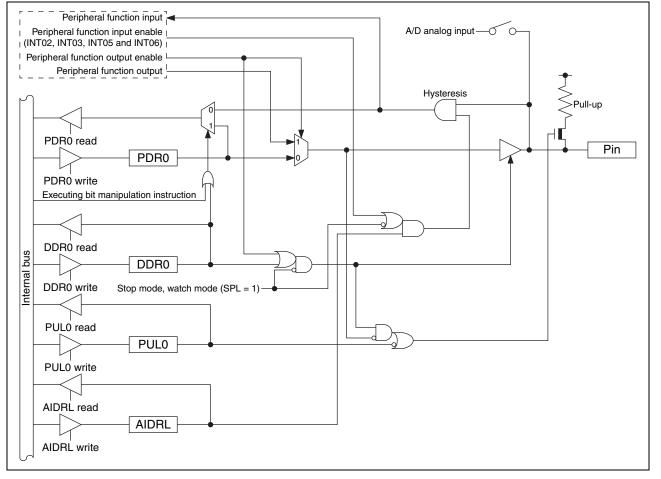
- External interrupt circuit input pin (INT03)
- 8/10-bit A/D converter analog input pin (AN03)
- LIN-UART data output pin (SOT)
- P05/INT05/AN05/TO00 pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT05)
 - 8/10-bit A/D converter analog input pin (AN05)
 - 8/16-bit composite timer ch. 0 output pin (TO00)
- P06/INT06/AN06/TO01 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT06)
- 8/10-bit A/D converter analog input pin (AN06)
- 8/16-bit composite timer ch. 0 output pin (TO01)



• Block diagram of P02/INT02/AN02/SCK, P03/INT03/AN03/SOT, P05/INT05/AN05/TO00 and P06/INT06/AN06/TO01





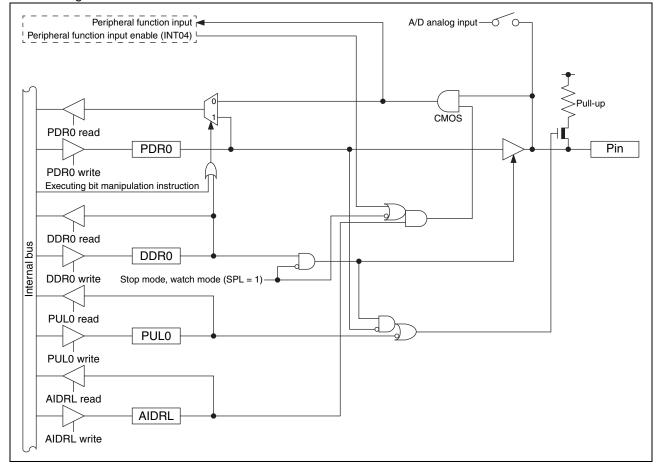


• P04/INT04/AN04/SIN/EC0 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT04)
- 8/10-bit A/D converter analog input pin (AN04)
- LIN-UART data input pin (SIN)
- 8/16-bit composite timer ch. 0 clock input pin (EC0)

• Block diagram of P04/INT04/AN04/SIN/EC0



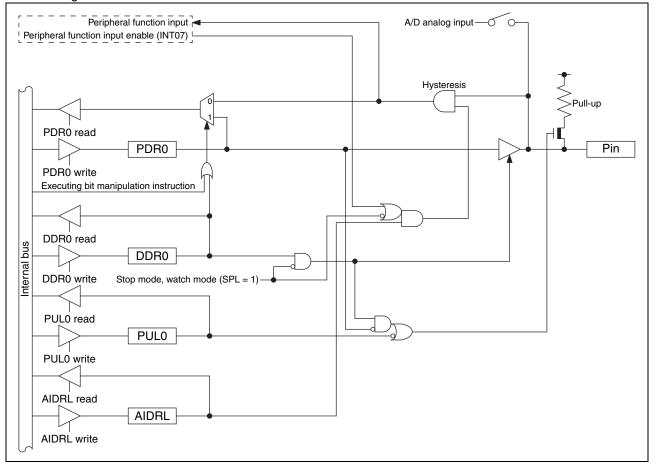


• P07/INT07/AN07 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT07)
- 8/10-bit A/D converter analog input pin (AN07)

Block diagram of P07/INT07/AN07





15.1.3 Port 0 registers

Port 0 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write					
PDR0	0	Pin state is "L" level.	PDR0 value is "0".	As output port, outputs "L" level.					
FDRU	1	Pin state is "H" level.	PDR0 value is "1".	As output port, outputs "H" level.					
DDR0	0	Port input enabled							
DDRU	1	Port output enabled							
PUL0	0		Pull-up disabled						
FOLO	1	Pull-up enabled							
AIDRL	0		Analog input enable	ed					
AIDRE	1		Port input enabled						

• Correspondence between registers and pins for port 0

	Correspondence between related register bits and pins										
Pin name	P07	P06	P05	P04	P03	P02	P01	P00			
PDR0			Lac		L:40		L:14	L:40			
DDR0	bit7	bit6 bit5		bit4		bit2					
PUL0	DILT		DIL4	bit3	DILZ	bit1	bit0				
AIDRL											

15.1.4 Port 0 operations

Operation as an output port

- A pin becomes an output port if the bit in the DDR0 register corresponding to that pin is set to "1".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- When a pin is used as an output port, it outputs the value of the PDR0 register to external pins.
- If data is written to the PDR0 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDR0 register returns the PDR0 register value.

• Operation as an input port

- A pin becomes an input port if the bit in the DDR0 register corresponding to that pin is set to "0".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- When using a pin shared with the analog input function as an input port, set the corresponding bit in the A/D input disable register (lower) (AIDRL) to "1".
- If data is written to the PDR0 register, the value is stored in the output latch but is not output to the pin set as an input port.
- Reading the PDR0 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR0 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR0 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.



- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR0 register corresponding to the input pin of a peripheral function to "0".
 - When using a pin shared with the analog input function as another peripheral function input pin, configure it as an input port by setting the bit in the AIDRL register corresponding to that pin to "1".
 - Reading the PDR0 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.

• Operation at reset

If the CPU is reset, all bits in the DDR0 register are initialized to "0" and port input is enabled. As for a pin shared with analog input, its port input is disabled because the AIDRL register is initialized to "0".

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop
 mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR0 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input is enabled for the external interrupt (INT00 to INT07), the input is enabled and not
 blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation as an analog input pin
 - Set the bit in the DDR0 register bit corresponding to the analog input pin to "0" and the bit corresponding to that pin in the AIDRL register to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions. In addition, set the corresponding bit in the PUL0 register to "0".
- Operation as an external interrupt input pin
 - Set the bit in the DDR0 register corresponding to the external interrupt input pin to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - The pin value is always input to the external interrupt circuit. When using a pin for a function other than the interrupt, disable the external interrupt function corresponding to that pin.
- Operation of the pull-up register

Setting the bit in the PUL0 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL0 register.

- Operation as a comparator input pin (only for P00 and P01)
 - Set the bit in the AIDRL register corresponding to the comparator input pin to "0".
 - Regardless of the value of the PDR0 register and that of the DDR0 register, if the comparator analog input enable bit in the comparator control register (CMR0C:VCID) is set to "0", the comparator input function is enabled.
 - To disable the comparator input function, set the VCID bit to "1".
 - For details of the comparator, refer to "CHAPTER 27 COMPARATOR" in "New 8FX MB95630H Series Hardware Manual".



15.2 Port 1

Port 1 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.2.1 Port 1 configuration

- Port 1 is made up of the following elements.
- General-purpose I/O pins/peripheral function I/O pins
- Port 1 data register (PDR1)
- Port 1 direction register (DDR1)
- Port 1 pull-up register (PUL1)

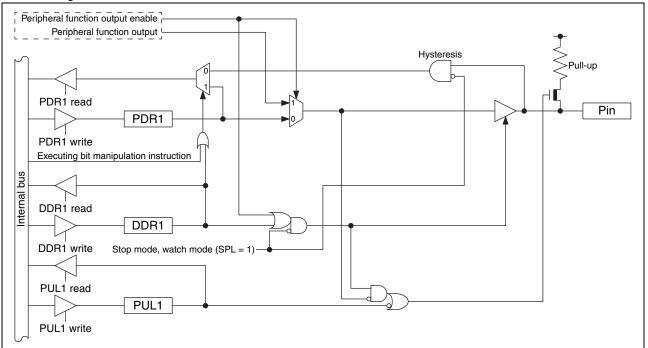
15.2.2 Block diagrams of port 1

- P10/PPG10/CMP0_O pin
 - This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 1 output pin (PPG10)
 - Comparator digital output pin (CMP0_O)
- P11/PPG11 pin
 - This pin has the following peripheral function:
 - 8/16-bit PPG ch. 1 output pin (PPG11)
- P13/PPG00 pin
 - This pin has the following peripheral function:
 - 8/16-bit PPG ch. 0 output pin (PPG00)
- P15/UO0/PPG20 pin

This pin has the following peripheral functions:

- UART/SIO ch. 0 data output pin (UO0)
- 8/16-bit PPG ch. 2 output pin (PPG20)





• Block diagram of P10/PPG10/CMP0_O, P11/PPG11, P13/PPG00 and P15/UO0/PPG20

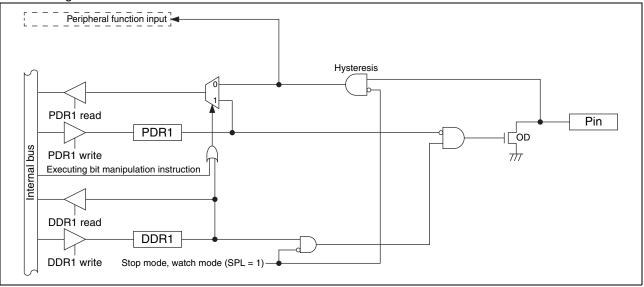


• P12/DBG/EC0 pin

This pin has the following peripheral functions:

- DBG input pin (DBG)
- 8/16-bit composite timer ch. 0 clock input pin (EC0)

• Block diagram of P12/DBG/EC0

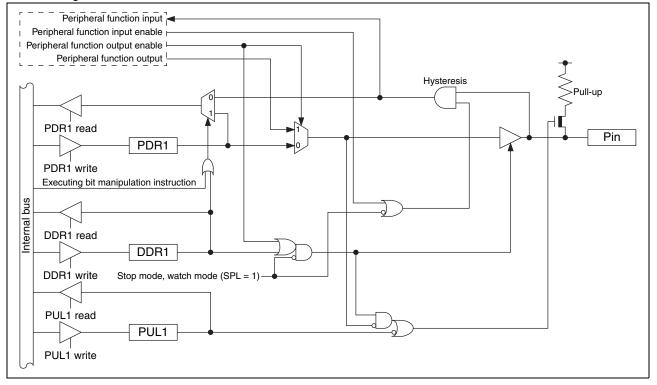


• P14/UCK0/PPG01 pin

- This pin has the following peripheral functions:
- UART/SIO ch. 0 clock I/O pin (UCK0)
- 8/16-bit PPG ch. 0 output pin (PPG01)



Block diagram of P14/UCK0/PPG01



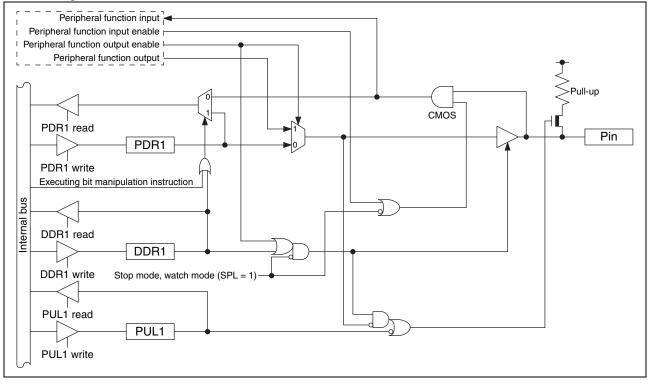


• P16/UI0/PPG21 pin

This pin has the following peripheral functions:

- UART/SIO ch. 0 data input pin (UI0)
- 8/16-bit PPG ch. 2 output pin (PPG21)

Block diagram of P16/UI0/PPG21



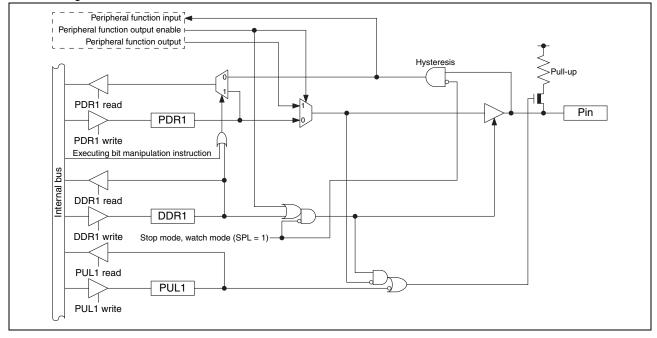
• P17/TO1/SNI0 pin

This pin has the following peripheral functions:

- 16-bit reload timer ch. 1 output pin (TO1)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI0)



• Block diagram of P17/TO1/SNI0





15.2.3 Port 1 registers

Port 1 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write				
PDR1	0	Pin state is "L" level.	PDR1 value is "0".	As output port, outputs "L" level.				
FURI	1	Pin state is "H" level.	PDR1 value is "1".	As output port, outputs "H" level.*				
DDR1	0		Port input enabled					
DDRT	1		Port output enabled					
	0	Pull-up disabled						
PUL1	1		Pull-up enabled					

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

• Correspondence between registers and pins for port 1

		Correspondence between related register bits and pins										
Pin name	P17	P16	P15	P14	P13	P12	P11	P10				
PDR1												
DDR1	bit7	bit6	bit5	bit4	bit3	bit2*	bit1	bit0				
PUL1												

*: Though P12 has no pull-up function, bit2 in the PUL1 register can still be accessed. The operation of P12 is not affected by the setting of bit2 in the PUL1 register.

15.2.4 Port 1 operations

• Operation as an output port

- A pin becomes an output port if the bit in the DDR1 register corresponding to that pin is set to "1".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- When a pin is used as an output port, it outputs the value of the PDR1 register to external pins.
- If data is written to the PDR1 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDR1 register returns the PDR1 register value.

• Operation as an input port

- A pin becomes an input port if the bit in the DDR1 register corresponding to that pin is set to "0".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- If data is written to the PDR1 register, the value is stored in the output latch but is not output to the pin set as an input port.
- Reading the PDR1 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR1 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR1 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR1 register corresponding to the input pin of a peripheral function



to "0".

- Reading the PDR1 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDR1 register are initialized to "0" and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop
 mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR1 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input of P14/UCK0 and P16/UI0 is enabled by the external interrupt control register ch. 0
 (EIC00) of the external interrupt circuit and the interrupt pin selection circuit control register (WICR) of the interrupt
 pin selection circuit, the input is enabled and is not blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

• Operation of the pull-up register

Setting the bit in the PUL1 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL1 register.

15.3 Port 6

Port 6 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.3.1 Port 6 configuration

Port 6 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 6 data register (PDR6)
- Port 6 direction register (DDR6)
- Port 6 pull-up register (PUL6)

15.3.2 Block diagrams of port 6

P60/INT08/SDA/DTTI pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT08)
- I²C bus interface ch. 0 data I/O pin (SDA)
- MPG waveform sequencer input pin (DTTI)

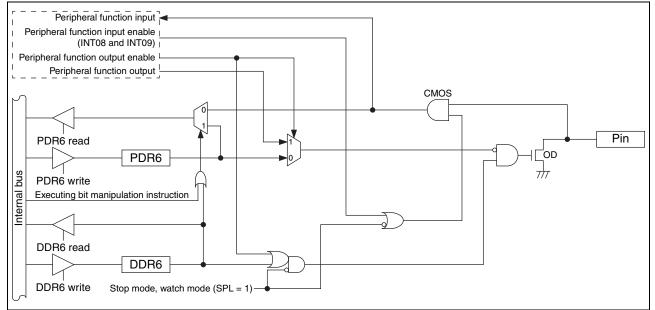
• P61/INT09/SCL/TI1 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT09)
- I²C bus interface ch. 0 clock I/O pin (SCL)
- 16-bit reload timer ch. 1 input pin (TI1)



Block diagram of P60/INT08/SDA/DTTI and P61/INT09/SCL/TI1



• P62/TO10/PPG00/OPT0 pin

This pin has the following peripheral functions:

- 8/16-bit composite timer ch. 1 output pin (TO10)
- 8/16-bit PPG ch. 0 output pin (PPG00)
- MPG waveform sequencer output pin (OPT0)

• P63/TO11/PPG01/OPT1 pin

This pin has the following peripheral functions:

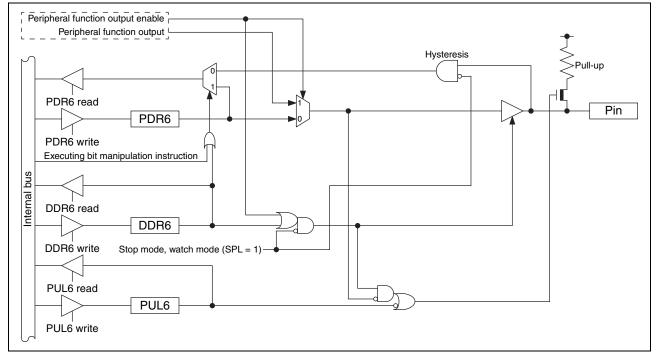
- 8/16-bit composite timer ch. 1 output pin (TO11)
- 8/16-bit PPG ch. 0 output pin (PPG01)
- MPG waveform sequencer output pin (OPT1)
- P65/PPG11/OPT3 pin

This pin has the following peripheral functions:

- 8/16-bit PPG ch. 1 output pin (PPG11)
- MPG waveform sequencer output pin (OPT3)
- P66/PPG20/PPG1/OPT4 pin
 - This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 2 output pin (PPG20)
 - 16-bit PPG timer ch. 1 output pin (PPG1)
 - MPG waveform sequencer output pin (OPT4)
- Block diagram of P62/TO10/PPG00/OPT0, P63/TO11/PPG01/OPT1, P65/PPG11/OPT3 and



P66/PPG20/PPG1/OPT4



• P64/EC1/PPG10/OPT2 pin

This pin has the following peripheral functions:

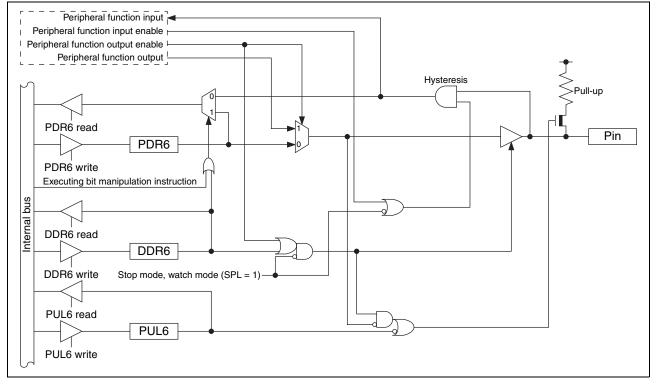
- 8/16-bit composite timer ch. 1 clock input pin (EC1)
- 8/16-bit PPG ch. 1 output pin (PPG10)
- MPG waveform sequencer output pin (OPT2)

• P67/PPG21/TRG1/OPT5 pin

- This pin has the following peripheral functions:
- 8/16-bit PPG ch. 2 output pin (PPG21)
- 16-bit PPG timer ch. 1 trigger input pin (TRG1)
- MPG waveform sequencer output pin (OPT5)



• Block diagram of P64/EC1/PPG10/OPT2 and P67/PPG21/TRG1/OPT5



15.3.3 Port 6 registers

• Port 6 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write				
PDR6	0	Pin state is "L" level.	PDR6 value is "0".	As output port, outputs "L" level.				
FDIXO	1	Pin state is "H" level.	PDR6 value is "1".	As output port, outputs "H" level.*				
DDR6	0		Port input enabled					
DDI(0	1		Port output enabled					
PUL6	0		Pull-up disabled					
POLO	1		Pull-up enabled					

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

• Correspondence between registers and pins for port 6

	Correspondence between related register bits and pins									
Pin name	P67	P66	P65	P64	P63	P62	P61	P60		
PDR6							bit1	bit0		
DDR6	bit7	bit6	bit5	bit4	bit3	bit2	DILI	Dito		
PUL6							-	-		



15.3.4 Port 6 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR6 register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR6 register to external pins.
 - If data is written to the PDR6 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR6 register returns the PDR6 register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDR6 register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDR6 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR6 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR6 register even if the peripheral function output is enabled. Therefore, the
 output value of a peripheral function can be read by the read operation on the PDR6 register. However, if the readmodify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR6 register corresponding to the input pin of a peripheral function to "0".
 - Reading the PDR6 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.

Operation at reset If the CPU is reset, all bits in the DDR6 register are initialized to "0" and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop
 mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR6 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input from the external interrupt (INT08, INT09) is enabled, or if the interrupt input of P64/EC1
 and P67/TRG1 is enabled by the external interrupt control register ch. 0 (EIC00) of the external interrupt circuit and
 the interrupt pin selection circuit control register (WICR) of the interrupt pin selection circuit, the input is enabled
 and is not blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register

Setting the bit in the PUL6 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL6 register.



15.4 Port F

Port F is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.4.1 Port F configuration

- Port F is made up of the following elements.
- General-purpose I/O pins/peripheral function I/O pins
- Port F data register (PDRF)
- Port F direction register (DDRF)

15.4.2 Block diagrams of port F

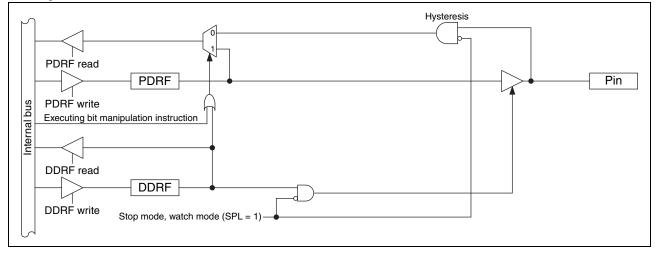
• PF0/X0 pin

This pin has the following peripheral function:

- Main clock input oscillation pin (X0)
- PF1/X1 pin

This pin has the following peripheral function:

- Main clock I/O oscillation pin (X1)
- Block diagram of PF0/X0 and PF1/X1

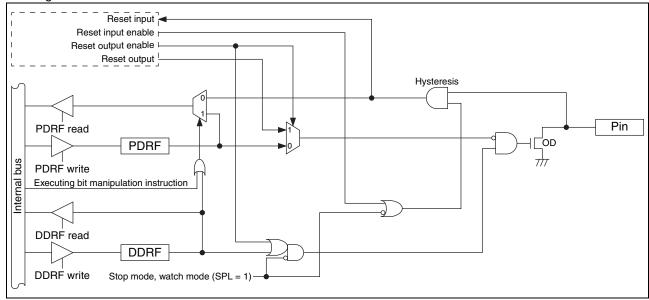




• PF2/RST pin

- This pin has the following peripheral function:
- Reset pin (RST)

Block diagram of PF2/RST



15.4.3 Port F registers

• Port F register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write				
PDRF	0	Pin state is "L" level.	PDRF value is "0".	As output port, outputs "L" level.				
FDIN	1	Pin state is "H" level.	PDRF value is "1".	As output port, outputs "H" level.*				
DDRF	0		Port input enabled					
DDRF	1		Port output enable	d				

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

· Correspondence between registers and pins for port F

	Correspondence between related register bits and pins									
Pin name	-	-	-	-	-	PF2*	PF1	PF0		
PDRF		_	_		_	bit2	bit1	bit0		
DDRF	-	-	-	-	-	UILZ	DILI	DILU		

*: PF2/RST is the dedicated reset pin on MB95F632H/F633H/F634H/F636H.

15.4.4 Port F operations

• Operation as an output port

- A pin becomes an output port if the bit in the DDRF register corresponding to that pin is set to "1".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- When a pin is used as an output port, it outputs the value of the PDRF register to external pins.
- If data is written to the PDRF register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDRF register returns the PDRF register value.



- Operation as an input port
 - A pin becomes an input port if the bit in the DDRF register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDRF register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDRF register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRF register, the PDRF register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDRF register are initialized to "0" and port input is enabled.

- · Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRF register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

15.5 Port G

Port G is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.5.1 Port G configuration

- Port G is made up of the following elements.
- General-purpose I/O pins/peripheral function I/O pins
- Port G data register (PDRG)
- Port G direction register (DDRG)
- Port G pull-up register (PULG)

15.5.2 Block diagram of port G

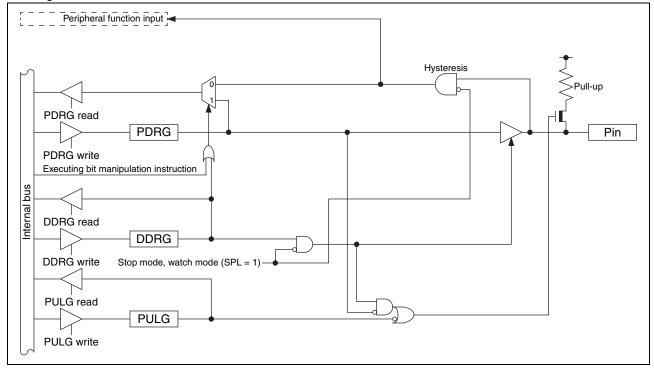
PG1/X0A/SNI1 pin

This pin has the following peripheral functions:

- Subclock input oscillation pin (X0A)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI1)
- PG2/X1A/SNI2 pin
 - This pin has the following peripheral functions:
 - Subclock I/O oscillation pin (X1A)
 - Trigger input pin for the position detection function of the MPG waveform sequencer (SNI2)



• Block diagram of PG1/X0A/SNI1 and PG2/X1A/SNI2



15.5.3 Port G registers

• Port G register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write				
PDRG	0	Pin state is "L" level.	PDRG value is "0".	As output port, outputs "L" level.				
FDRG	1	Pin state is "H" level.	PDRG value is "1".	As output port, outputs "H" level.				
DDRG	0		Port input enabled					
DDKG	1		Port output enabled					
PULG	0		Pull-up disabled					
FOLG	1		Pull-up enabled					

• Correspondence between registers and pins for port G

		Correspondence between related register bits and pins										
Pin name	-	-	-	-	-	PG2	PG1	-				
PDRG												
DDRG	-	-	-	-	-	bit2	bit1	-				
PULG												

15.5.4 Port G operations

• Operation as an output port

- A pin becomes an output port if the bit in the DDRG register corresponding to that pin is set to "1".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- When a pin is used as an output port, it outputs the value of the PDRG register to external pins.



- If data is written to the PDRG register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDRG register returns the PDRG register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDRG register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDRG register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDRG register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDRG register corresponding to the input pin of a peripheral function to "0".
 - Reading the PDRG register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDRG register are initialized to "0" and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRG register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register

Setting the bit in the PULG register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PULG register.



16. Interrupt Source Table

	Interrupt		r table ress		pt level register	Priority order of interrupt sources
Interrupt source	request number	Upper	Lower	Register	Bit	of the same level (occurring simultaneously)
External interrupt ch. 0	IRQ00	0xFFFA	0xFFFB	ILR0	L00 [1:0]	High
External interrupt ch. 4				ILINO	L00[1.0]	
External interrupt ch. 1	IRQ01	0xFFF8	0xFFF9	ILR0	L01 [1:0]	
External interrupt ch. 5		0/1110	0/1113			
External interrupt ch. 2	IRQ02	0xFFF6	0xFFF7	ILR0	L02 [1:0]	
External interrupt ch. 6	INQUZ	UXFFFU	UXFFF7	ILKU	LUZ [1.0]	
External interrupt ch. 3	IRQ03	0xFFF4	0xFFF5	ILR0	L03 [1:0]	
External interrupt ch. 7	IRQUS	UXFFF4	UXFFF5	ILKU	LU3 [1.0]	
UART/SIO ch. 0	IRQ04	0xFFF2	0xFFF3	ILR1	1.04 [1:0]	
MPG (DTTI)	IKQ04	UXFFFZ	UXFFF3	ILKI	L04 [1:0]	
8/16-bit composite timer ch. 0	IRQ05					
(lower)	IRQUS	0xFFF0	0xFFF1	ILR1	L05 [1:0]	
8/16-bit composite timer ch. 0		0xFFEE			1.00 [4:0]	
(upper)	IRQ06	UXFFEE	0xFFEF	ILR1	L06 [1:0]	
LIN-UART (reception)	IRQ07	0xFFEC	0xFFED	ILR1	L07 [1:0]	
LIN-UART (transmission)	IRQ08	0xFFEA	0xFFEB	ILR2	L08 [1:0]	
8/16-bit PPG ch. 1 (lower)	IRQ09	0xFFE8	0xFFE9	ILR2	L09 [1:0]	
8/16-bit PPG ch. 1 (upper)	IRQ10	0xFFE6	0xFFE7	ILR2	L10 [1:0]	
8/16-bit PPG ch. 2 (upper)	IRQ11	0xFFE4	0xFFE5	ILR2	L11 [1:0]	
8/16-bit PPG ch. 0 (upper)	IRQ12	0xFFE2	0xFFE3	ILR3	L12 [1:0]	
8/16-bit PPG ch. 0 (lower)	IRQ13	0xFFE0	0xFFE1	ILR3	L13 [1:0]	
8/16-bit composite timer ch. 1						
(upper)	IRQ14	0xFFDE	0xFFDF	ILR3	L14 [1:0]	
8/16-bit PPG ch. 2 (lower)	IRQ15	0xFFDC	0xFFDD	ILR3	L15 [1:0]	
16-bit reload timer ch. 1			-			
MPG (write timing/compare clear)	IRQ16	0xFFDA	0xFFDB	ILR4	L16 [1:0]	
I ² C bus interface	1					
16-bit PPG timer ch. 1						
MPG (position detection/compare	IRQ17	0xFFD8	0xFFD9	ILR4	L17 [1:0]	
interrupt)			••••••		[]	
8/10-bit A/D converter	IRQ18	0xFFD6	0xFFD7	ILR4	L18 [1:0]	
Time-base timer	IRQ19	0xFFD4	0xFFD5	ILR4	L19 [1:0]	
Watch prescaler						
Comparator	IRQ20	0xFFD2	0xFFD3	ILR5	L20 [1:0]	
External interrupt ch. 8						
External interrupt ch. 9	IRQ21	0xFFD0	0xFFD1	ILR5	L21 [1:0]	
8/16-bit composite timer ch. 1						
(lower)	IRQ22	0xFFCE	0xFFCF	ILR5	L22 [1:0]	
Flash memory	IRQ23	0xFFCC	0xFFCD	ILR5	L23 [1:0]	Low



17. Pin States In Each Mode

Din nome	Normal		Stop	mode	Watch	mode	Or read
Pin name	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	On reset
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
PF0/X0	I/O port*4	I/O port*4	 Previous state kept Input blocked*2*4 	- Hi-Z - Input blocked*2*4	 Previous state kept Input blocked*2*4 	- Hi-Z - Input blocked*2*4	 Hi-Z Input enabled^{*1} (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
PF1/X1	I/O port*4	I/O port*4	 Previous state kept Input blocked*2*4 	- Hi-Z - Input blocked*2*4	 Previous state kept Input blocked*2*4 	- Hi-Z - Input blocked*2*4	 Hi-Z Input enabled*1 (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	_
PG1/X0A/ SNI1	I/O port*4/ peripheral func- tion I/O	I/O port*4/ peripheral func- tion I/O	 Previous state kept Input blocked*2*4 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2*4 	 Previous state kept Input blocked*2*4 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2*4 	 Hi-Z Input enabled*1 (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
PG2/X1A/ SNI2	I/O port*4/ peripheral function I/O	I/O port*4/ peripheral function I/O	 Previous state kept Input blocked*^{2*4} 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2*4 	 Previous state kept Input blocked*2*4 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2*4 	 Hi-Z Input enabled*1 (However, it does not function.)
PF2/RST	I/O port	Reset input	Reset input	Reset input	Reset input	Reset input	Reset input*3
P60/INT08/ SDA/DTTI			 Previous state kept Input blocked*² (However, an 	 Hi-Z Input blocked^{*2} (However, an external 	 Previous state kept Input blocked^{*2} (However, an 	 Hi-Z Input blocked*² (However, an external 	- Hi-Z - Input
P61/INT09/ SCL/TI1	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	external interrupt can be input when the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	external interrupt can be input when the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	enabled*1 (However, it does not function.)
P62/TO10/ PPG00/ OPT0 P63/TO11/ PPG01/ OPT1	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Hi-Z Input enabled*1 (However, it does not function.)





Pin name	Normal	Sleep mode	Stop	mode	Watch	mode	On reset
Pin name	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	On reset
P64/EC1/ PPG10/ OPT2	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z Input enabled*¹ (However, it does not function.)
P65/PPG11/ OPT3	I/O port/	I/O port/	- Previous state	- Hi-Z (However, the setting of	- Previous state	- Hi-Z (However, the setting of	 Hi-Z Input enabled^{*1}
P66/PPG1/ PPG20/ OPT4	peripheral function I/O	peripheral function I/O	kept - Input blocked*2	the pull-up control is effective.) - Input blocked*2	kept - Input blocked*2	the pull-up control is effective.) - Input blocked*2	(However, it does not function.)
P67/TRG1/ PPG21/ OPT5	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*² (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*² (However, an external interrupt can be input when the external interrupt request is enabled.) 	- Hi-Z - Input enabled*1 (However, it does not function.)
P10/PPG10/ CMP0_O P11/PPG11	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) 	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) 	 Hi-Z Input enabled*1 (However, it does not
P12/DBG/	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Input blocked*2 Hi-Z Input blocked*2 	 Previous state kept Input blocked*2 	 Input blocked*2 Hi-Z Input blocked*2 	function.) - Hi-Z - Input enabled*1 (However, it does not function.)
P13/PPG00	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Previous state kept Input blocked^{*2} 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Hi-Z Input enabled*1 (However, it does not function.)





Pin name	Normal	Sleep mode	Stop	mode	Watch	mode	On reset
Fin hame	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	Uniteset
P14/UCK0/ PPG01	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z Input enabled*1 (However, it does not function.)
P15/UO0/ PPG20	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Hi-Z Input enabled^{*1} (However, it does not function.)
P16/UI0/ PPG21	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Previous state kept Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	 Hi-Z Input enabled*1 (However, it does not function.)
P17/TO1/ SNI0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Previous state kept Input blocked*2 	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	 Hi-Z Input enabled*1 (However, it does not function.)
P00/INT00/ AN00/ CMP0_P			- Previous state	 Hi-Z (However, the setting of the pull-up 	- Previous state kept	 Hi-Z (However, the setting of the pull-up 	
	I/O port/ peripheral	I/O port/ peripheral	kept - Input blocked*2 (However, an external interrupt con	control is effective.) - Input blocked* ² (However, an	 Input blocked*2 (However, an external 	control is effective.) - Input blocked* ² (However, an	- Hi-Z
P02/INT02/ AN02/SCK	function I/O/ analog input	function I/O/ analog input	interrupt can be input when the external	external interrupt can be input when	interrupt can be input when the external	external interrupt can be input when	 Input blocked*2
P03/INT03/ AN03/SOT			interrupt request is enabled.)	the external interrupt request is enabled.)	interrupt request is enabled.)	the external interrupt request is enabled.)	



Pin name	Normal	Sleen mode	Stop	mode	Watch	On reset	
	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	Onneset
P04/INT04/ AN04/SIN/ EC0			- Previous state kept	 Hi-Z (However, the setting of the pull-up 	- Previous state kept	 Hi-Z (However, the setting of the pull-up 	
P05/INT05/ AN05/TO00	I/O port/	I/O port/	 Input blocked*2 (However, an 	control is effective.) - Input blocked*2	- Input blocked*2	control is effective.) - Input blocked*2	
P06/INT06/	peripheral function I/O/	peripheral function I/O/	external interrupt can be input when	(However, an external	external interrupt can be input when	(However, an external	 Hi-Z Input blocked*2
P07/INT07/ AN07	analog input	analog input	the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	biolicu

SPL: Pin state setting bit in the standby control register (STBC:SPL)

Hi-Z: High impedance

- *1: "Input enabled" means that the input function is enabled. While the input function is enabled, a pull-up or pull-down operation has to be performed in order to prevent leaks due to external input. If a pin is used as an output port, its pin state is the same as that of other ports.
- *2: "Input blocked" means direct input gate operation from the pin is disabled.
- *3: The PF2/RST pin stays at the state shown when configured as a reset pin.
- *4: The pin stays at the state shown when configured as a general-purpose I/O port.





18. Electrical Characteristics

18.1 Absolute Maximum Ratings

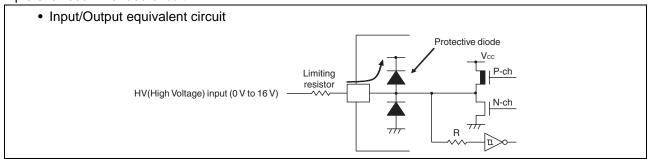
Parameter	Symbol	Rat	ing	Unit	Domorko
Farameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage*1	Vcc	Vss-0.3	Vss + 6	V	
Input voltage*1	Vi	Vss-0.3	Vss + 6	V	*2
Output voltage*1	Vo	V ss - 0.3	Vss + 6	V	*2
Maximum clamp current		-2	+2	mA	Applicable to specific pins*3
Total maximum clamp current	Σ Iclamp	_	20	mA	Applicable to specific pins*3
"L" level maximum output current	lol	_	15	mA	
"L" level average current	IOLAV1		4	mA	Other than P62 to P67 Average output current = operating current × operating ratio (1 pin)
	Iolav2		12		P62 to P67 Average output current = operating current × operating ratio (1 pin)
"L" level total maximum output current	Σ Iol	_	100	mA	
"L" level total average output current	Σ Iolav	_	37	mA	Total average output current = operating current × operating ratio (Total number of pins)
"H" level maximum output current	Іон	_	-15	mA	
"H" level average	Іонау1		-4	mA	Other than P62 to P67 Average output current = operating current × operating ratio (1 pin)
current	Іонау2		-8		P62 to P67 Average output current = operating current × operating ratio (1 pin)
"H" level total maximum output current	ΣІон	_	-100	mA	
"H" level total average output current	ΣІонаν		-47	mA	Total average output current = operating current × operating ratio (Total number of pins)
Power consumption	Pd	—	320	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

*1: These parameters are based on the condition that Vss is 0.0 V.

*2: V1 and V0 must not exceed Vcc + 0.3 V. V1 must not exceed the rated voltage. However, if the maximum current to/from an input is limited by means of an external component, the IcLAMP rating is used instead of the V1 rating.
*3: Specific pins: P00 to P07, P10, P11, P13 to P17, P62 to P67, PF0, PF1, PG1, PG2



- Use under recommended operating conditions.
- Use with DC voltage (current).
- The HV (High Voltage) signal is an input signal exceeding the Vcc voltage. Always connect a limiting resistor between the HV (High Voltage) signal and the microcontroller before applying the HV (High Voltage) signal.
- The value of the limiting resistor should be set to a value at which the current to be input to the microcontroller pin when the HV (High Voltage) signal is input is below the standard value, irrespective of whether the current is transient current or stationary current.
- When the microcontroller drive current is low, such as in low power consumption modes, the HV (High Voltage) input potential may pass through the protective diode to increase the potential of the Vcc pin, affecting other devices.
- If the HV (High Voltage) signal is input when the microcontroller power supply is off (not fixed at 0 V), since power is supplied from the pins, incomplete operations may be executed.
- If the HV (High Voltage) input is input after power-on, since power is supplied from the pins, the voltage of power supply may not be sufficient to enable a power-on reset.
- Do not leave the HV (High Voltage) input pin unconnected.
- Example of a recommended circuit:



WARNING: Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.



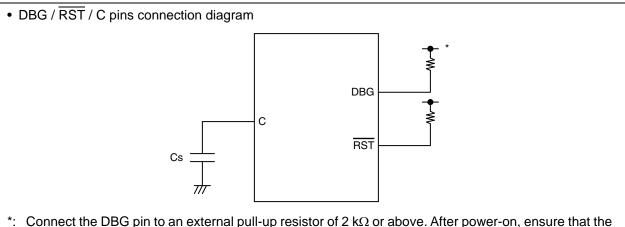
18.2 Recommended Operating Conditions

(Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks		
Falameter	Symbol	Min	Max	Unit	iteniai KS		
Power supply voltage	Vcc	2.4 ^{*1}	5.5	V	In normal operation		
Power supply vollage	VCC	2.3	5.5		Hold condition in stop mode		
Decoupling capacitor	Cs	0.022	1	μF	*2		
Operating temperature	TA	- 40	+85	°C	Other than on-chip debug mode		
	IA	+5	+35		On-chip debug mode		

*1: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used or when the on-chip debug mode is used.

*2: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs. For the connection to a decoupling capacitor Cs, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and Cs and the distance between Cs and the Vss pin when designing the layout of a printed circuit board.



- *: Connect the DBG pin to an external pull-up resistor of 2 kΩ or above. After power-on, ensure that the DBG pin does not stay at "L" level until the reset output is released. The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.
- WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition.

Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.



18.3 DC Characteristics

				(VCC -	Value		- 0.0 \	/, T _A = -40 °C to +8
Parameter	-		Condition	Min	Тур	Max	Unit	Remarks
	Vіні	P04, P16, P60, P61		0.7 Vcc	_	Vcc + 0.3	V	CMOS input level
"H" level input voltage	Vins	P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2	_	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input
	Vінм	PF2	—	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input
	Vili	P04, P16, P60, P61	—	Vss - 0.3		0.3 Vcc	V	CMOS input level
"L" level input voltage	Vils	P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2	_	Vss – 0.3	_	0.2 Vcc	V	Hysteresis input
	VILM	PF2		Vss-0.3	—	0.2 Vcc	V	Hysteresis input
Open-drain output application voltage	VD	P12, P60, P61, PF2	_	Vss – 0.3		Vss + 5.5	V	
"H" level output voltage	Voh1	Output pins other than P12, P62 to P67, PF2	Іон = -4 mA	Vcc – 0.5	_	_	V	
-	Vон2	P62 to P67	Iон = -8 mA	Vcc - 0.5	—	_	V	
"L" level output	Vol1	Output pins other than P62 to P67	loL = 4 mA	_	_	0.4	V	
voltage	Vol2	P62 to P67	lo∟ = 12 mA	—		0.4	V	
Input leak current (Hi-Z output leak current)	lu	All input pins	0.0 V < Vı < Vcc	-5	_	+5	μA	When the internal pull-up resistor is disabled
Internal pull-up resistor	Rpull	P00 to P07, P10, P11, P13 to P17, P62 to P67, PG1, PG2	V1 = 0 V	25	50	100	kΩ	When the internal pull-up resistor is enabled
Input capacitance	Cin	Other than Vcc and Vss	f = 1 MHz	—	5	15	pF	



		Sumhal Din nama Ca			Value			_
Parameter	Symbol	Pin name	Condition	Min	Typ*1	Max*2	Unit	Remarks
		F	Fсн = 32 MHz Fмр = 16 MHz		3.6	5.8	mA	Except during Flash memory programming and erasing
	lcc		Main clock mode (divided by 2)		7.5	13.8	mA	During Flash memory programming and erasing
				_	4.1	9.1	mA	At A/D conversion
	lccs		$F_{CH} = 32 \text{ MHz}$ $F_{MP} = 16 \text{ MHz}$ Main sleep mode (divided by 2)	_	1.3	3	mA	
	Iccl	Vcc (External clock operation)	$F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Subclock mode (divided by 2) $T_A = +25^{\circ}C$	_	49	145	μA	
Power supply	Iccls		$F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Subsleep mode (divided by 2) $T_A = +25^{\circ}C$	_	10	15	μA	In deep standby mode
current* ³	Ісст		$F_{CL} = 32 \text{ kHz}$ Watch mode Main stop mode $T_A = +25^{\circ}C$	_	7	13	μA	In deep standby mode
	ICCMPLL		$F_{MCRPLL} = 16 \text{ MHz}$ $F_{MP} = 16 \text{ MHz}$ Main CR PLL clock mode (multiplied by 4) $T_A = +25^{\circ}C$	_	4.7	6.8	mA	
	ICCMCR	Vcc	F _{CRH} = 4 MHz F _{MP} = 4 MHz Main CR clock mode	_	1.1	4.6	mA	
	ICCSCR		Sub-CR clock mode (divided by 2) T _A = +25°C	_	58.1	230	μA	
	Ісстѕ	Vcc (External clock	$F_{CH} = 32 \text{ MHz}$ Time-base timer mode $T_A = +25^{\circ}\text{C}$		345	395	μA	In deep standby mode
	Іссн	operation)	Substop mode T _A = +25°C		6	10	μA	In deep standby mode

(Vcc = 5.0 V±10%, Vss = 0.0 V, T_A = -40 °C to +85°C)



								-
Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
T arameter	Symbol	i in name	Condition	Min	Typ*1	Max*2	onic	Remarks
	Iv		Current consumption of the comparator	_	60	160	μA	
	Ilvd		Current consumption of the low-voltage detection circuit	_	4	7	μA	
Power	Іскн		Current consumption of the main CR oscillator	_	240	320	μA	
supply current*3	Icrl	Vcc	Current consumption of the sub-CR oscillator oscillating at 100 kHz	_	7	20	μA	
	Instby		Current consumption difference between normal standby mode and deep standby mode $T_A = +25^{\circ}C$	_	20	30	μΑ	

 $(Vcc = 5.0 V \pm 10\%, Vss = 0.0 V, T_A = -40 °C to +85°C)$

*1: $V_{CC} = 5.0 \text{ V}, \text{ T}_{A} = +25^{\circ}\text{C}$

*2: Vcc = 5.5 V, T_A = +85°C (unless otherwise specified)

- *3: The power supply current is determined by the external clock. When the low-voltage detection circuit is selected, the power supply current is the sum of adding the current consumption of the low-voltage detection circuit (ILVD) to one of the values from Icc to IccH. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current is the sum of adding up the current consumption of the low-voltage detection circuit (ILVD), the current consumption of the CR oscillators (ICRH, ICRL) and a specified value. In on-chip debug mode, the CR oscillator (ICRH) and the low-voltage detection circuit are always in operation, and current consumption therefore increases accordingly.
 - See "4. AC Characteristics Clock Timing" for FCH, FCL, FCRH and FMCRPLL.
 - See "4. AC Characteristics Source Clock/Machine Clock" for FMP and FMPL.
 - The power supply current value in standby mode is measured in deep standby mode. The current consumption in normal standby is higher than that in deep standby mode. The power supply current value in normal standby can be found by adding the current consumption difference between normal standby mode and deep standby mode (INSTBY) to the power supply current value in deep standby mode. For details of normal standby and deep standby mode, refer to "CHAPTER 3 CLOCK CONTROLLER" in "New 8FX MB95630H Series Hardware Manual".



18.4 AC Characteristics

18.4.1 Clock Timing

$(Vcc = 2.4 V \text{ to } 5.5 V, Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

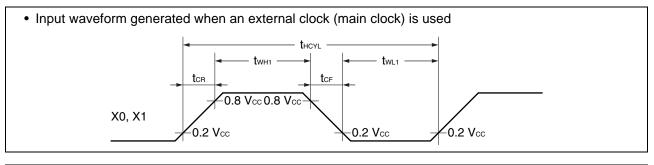
_					Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
	Fсн	X0, X1	_	1	—	16.25	MHz	When the main oscillation circuit is used
	ГСН	X0	X1: open	1	_	12	MHz	When the main external clock
		X0, X1	*	1	_	32.5	MHz	is used
				3.92	4	4.08	MHz	Operating conditions • The main CR clock is used. • $0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
	Fcrh	_	_	3.8	4	4.2	MHz	 Operating conditions The main CR clock is used. -40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
				7.84	8	8.16	MHz	• $0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
				7.6	8	8.4	MHz	$\begin{array}{l} \text{Operating conditions}\\ \bullet \ \text{PLL multiplication rate: 2}\\ \bullet \ - 40 \ ^{\circ}\text{C} \leq \text{T}_{\text{A}} < 0 \ ^{\circ}\text{C},\\ + 70 \ ^{\circ}\text{C} < \text{T}_{\text{A}} \leq + 85 \ ^{\circ}\text{C} \end{array}$
				9.8	10	10.2	MHz	Operating conditions • PLL multiplication rate: 2.5 • $0^{\circ}C \le T_A \le +70^{\circ}C$
Clock frequency				9.5	10	10.5	MHz	Operating conditions • PLL multiplication rate: 2.5 • $-40 \ ^{\circ}C \le T_A < 0 \ ^{\circ}C,$ $+70 \ ^{\circ}C < T_A \le +85 \ ^{\circ}C$
	FMCRPLL	RPLL —		11.76	12	12.24	MHz	Operating conditions • PLL multiplication rate: 3 • $0^{\circ}C \le T_A \le +70^{\circ}C$
				11.4	12	12.6	MHz	$\begin{array}{l} \hline \text{Operating conditions} \\ \bullet \ \text{PLL multiplication rate: 3} \\ \bullet \ -40 \ ^{\circ}\text{C} \leq \text{T}_{\text{A}} < 0 \ ^{\circ}\text{C}, \\ +70 \ ^{\circ}\text{C} < \text{T}_{\text{A}} \leq +85 \ ^{\circ}\text{C} \end{array}$
				15.68	16	16.32	MHz	Operating conditions • PLL multiplication rate: 4 • $0^{\circ}C \le T_A \le +70^{\circ}C$
				15.2	16	16.8	MHz	Operating conditions • PLL multiplication rate: 4 • $-40 \ ^{\circ}C \le T_A < 0 \ ^{\circ}C,$ $+70 \ ^{\circ}C < T_A \le +85 \ ^{\circ}C$
	Fc∟	X0A, X1A			32.768	_	kHz	When the suboscillation circuit is used
	FCL	70A, ATA		_	32.768	_	kHz	When the sub-external clock is used
	FCRL	_	_	50	100	150	kHz	When the sub-CR clock is used

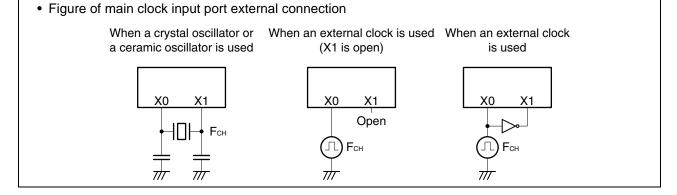


Parameter	Symbol	Din namo	Condition		Value		Unit	Remarks
Farameter	Symbol		Condition	Min	Тур	Max	Unit	Remarks
		X0, X1		61.5		1000	ns	When the main oscillation circuit is used
Clock cycle	t HCYL	X0	X1: open	83.4		1000	ns	When an external clock is
time		X0, X1	*	30.8		1000	ns	used
	t LCYL	X0A, X1A			30.5		μs	When the subclock is used
		X0	X1: open	33.4			ns	When an external clock is
Input clock pulse width	twH1, twL1	X0, X1	*	12.4				used, the duty ratio should
	twh2, twl2	X0A		_	15.2		μs	range between 40% and 60%.
Input clock		X0, X0A	X1: open	_		5	ns	When an external clock is
rising time and falling time		X0, X1, X0A, X1A	*		_	5		used
CR oscillation	tскнжк	_	—		_	50	μs	When the main CR clock is used
start time	t CRLWK		_	_	_	30	μs	When the sub-CR clock is used
PLL oscillation start time	t MCRPLLWK	_	—	—	—	100	μs	When the main CR PLL clock is used

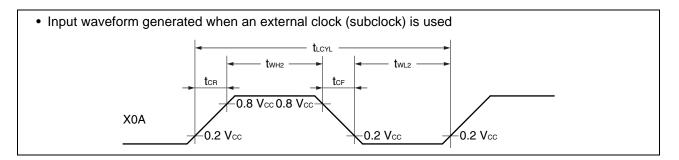
 $(Vcc = 2.4 V \text{ to } 5.5 V, Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

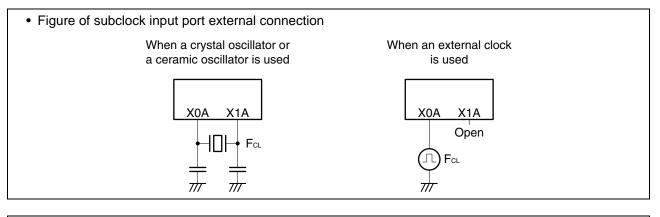
*: The external clock signal is input to X0 and the inverted external clock signal to X1.

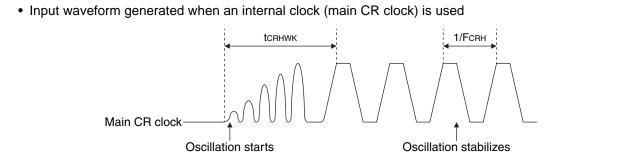


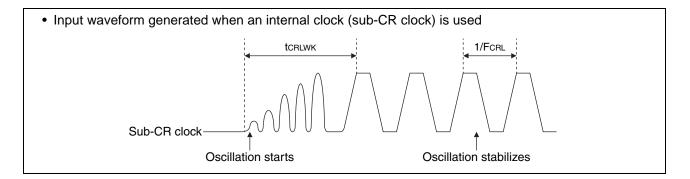




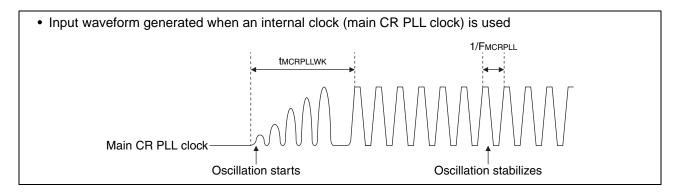












18.4.2 Source Clock/Machine Clock

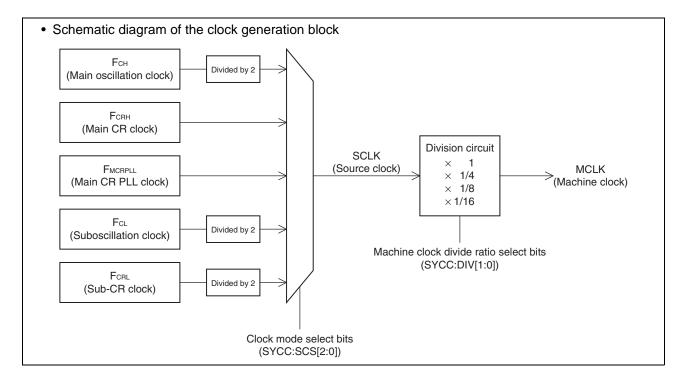
(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, T_A = -40°C to +85°C)

Parameter	Symbol	Pin		Value		Unit	Remarks
Farameter	Symbol	name	Min	Тур	Мах	Unit	Remarks
			61.5	_	2000	ns	When the main external clock is used Min: $F_{CH} = 32.5 \text{ MHz}$, divided by 2 Max: $F_{CH} = 1 \text{ MHz}$, divided by 2
Source clock cycle time*1	t sclk	_	62.5	_	250	ns	When the main CR clock is used Min: Fcrн = 4 MHz, multiplied by 4 Max: Fcrн = 4 MHz, no division
				61		μs	When the suboscillation clock is used $F_{CL} = 32.768 \text{ kHz}$, divided by 2
				20		μs	When the sub-CR clock is used $F_{CL} = 100 \text{ kHz}$, divided by 2
	Fsp		0.5		16.25	MHz	When the main oscillation clock is used
Source clock	F 5P		_	4	_	MHz	When the main CR clock is used
frequency		—	_	16.384	_	kHz	When the suboscillation clock is used
	Fspl			50		kHz	When the sub-CR clock is used $F_{CRL} = 100 \text{ kHz}$, divided by 2
			61.5	_	32000	ns	When the main oscillation clock is used Min: Fsp = 16.25 MHz, no division Max: Fsp = 0.5 MHz, divided by 16
Machine clock cycle time* ² (minimum	tмськ		250	_	4000	ns	When the main CR clock is used Min: Fsp = 4 MHz, no division Max: Fsp = 4 MHz, divided by 16
instruction execution time)	LIVIULK	_	61	_	976.5	μs	When the suboscillation clock is used Min: FspL = 16.384 kHz, no division Max: FspL = 16.384 kHz, divided by 16
			20	_	320	μs	When the sub-CR clock is used Min: FspL = 50 kHz, no division Max: FspL = 50 kHz, divided by 16

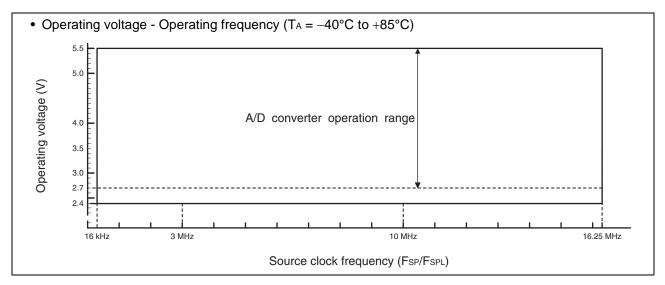


Parameter	Symbol	Pin		Value	e Uni		Remarks
Farameter	Symbol	name	Min	Тур	Max	Unit	Remarks
	Емр		0.031	—	16.25	MHz	When the main oscillation clock is used
Machine clock	IMP		0.25	_	16	MHz	When the main CR clock is used
frequency			1.024	_	16.384	kHz	When the suboscillation clock is used
	FMPL		3.125		50	kHz	When the sub-CR clock is used FcRL = 100 kHz

- *1: This is the clock before it is divided according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). This source clock is divided to become a machine clock according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). In addition, a source clock can be selected from the following.
 - Main clock divided by 2
 - Main CR clock
 - PLL multiplication of main CR clock (Select a multiplication rate from 2, 2.5, 3 and 4.)
 - Subclock divided by 2
 - Sub-CR clock divided by 2
- *2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.
 - Source clock (no division)
 - Source clock divided by 4
 - Source clock divided by 8
 - Source clock divided by 16





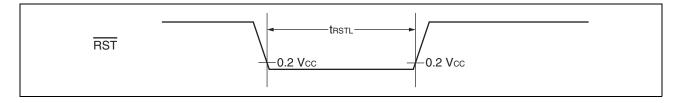


18.4.3 External Reset

(Vcc = 5.0 V±10%, Vss = 0.0 V, T_A = -40°C to +85°C)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max	Unit	Remarks
RST "L" level pulse width	t RSTL	2 tмс∟к*		ns	

*: See "Source Clock/Machine Clock" for tMCLK.

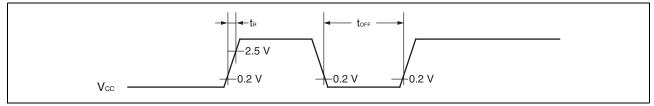




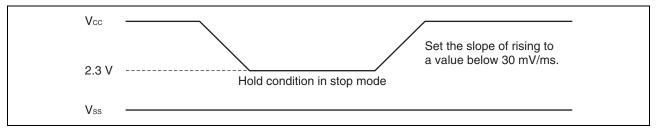
18.4.4 Power-on Reset

 $(Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Falameter	Symbol	Condition	Min	Мах	Unit		
Power supply rising time	tr			50	ms		
Power supply cutoff time	toff		1		ms	Wait time until power-on	



Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.

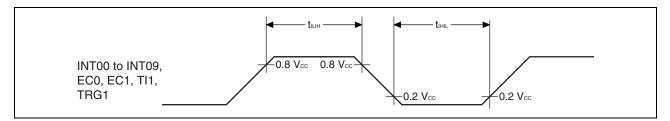


18.4.5 Peripheral Input Timing

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Va	Unit	
Farameter	Symbol	Fininanie	Min	Max	Unit
Peripheral input "H" pulse width	tı∟ıн	INT00 to INT09, EC0, EC1, TI1,	2 t MCLK*		ns
Peripheral input "L" pulse width	tını∟	TRG1	2 tмськ*		ns

*: See "Source Clock/Machine Clock" for tMCLK.





18.4.6 LIN-UART Timing

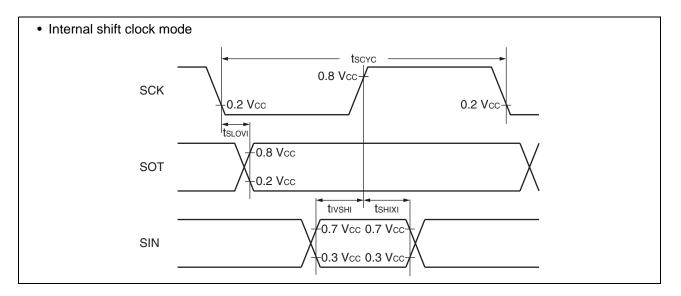
Sampling is executed at the rising edge of the sampling $clock^{*1}$, and serial clock delay is disabled^{*2}. (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

Parameter	Symbol	Pin name	Condition	Va	lue	Unit
Farameter	Symbol	Fin name	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 tmclk*3	—	ns
$SCK\!\!\downarrow ightarrow SOT$ delay time	tslovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN \rightarrow SCK \uparrow	t ivshi	SCK, SIN	operation output pin: C∟ = 80 pF + 1 TTL	tmclk*3 + 80	—	ns
$SCK^{\uparrow} \to valid SIN hold time$	tshixi	SCK, SIN		0	—	ns
Serial clock "L" pulse width	tslsh	SCK		3 tmclk*3-tr	—	ns
Serial clock "H" pulse width	tshsl	SCK		tмськ*3 + 10	—	ns
$SCK\!\!\downarrow ightarrow SOT$ delay time	t SLOVE	SCK, SOT	External clock	_	2 tмськ*3 + 60	ns
Valid SIN \rightarrow SCK \uparrow	tivshe	SCK, SIN	operation output pin:	30	—	ns
$SCK^{\uparrow} \to valid SIN hold time$	tshixe	SCK, SIN	C∟ = 80 pF + 1 TTL	tмськ*3 + 30	—	ns
SCK falling time	t⊧	SCK		—	10	ns
SCK rising time	tR	SCK		—	10	ns

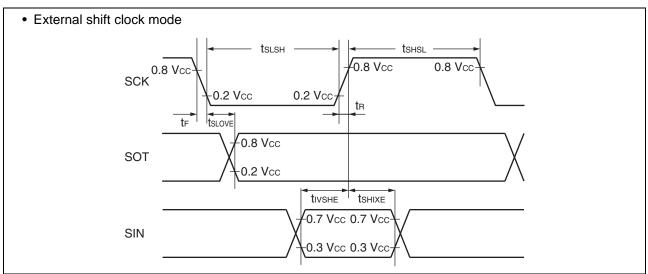
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock/Machine Clock" for tMCLK.







Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is disabled*2. (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

$(Vcc = 5.0 V \pm$	10%, Vss =	0.0 V, TA =	-40°C	to +85	5°C)

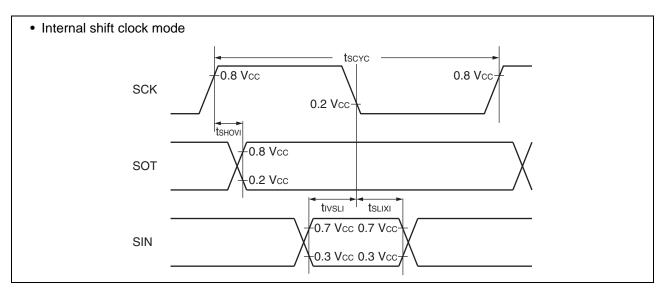
Parameter	Symbol	Pin name	Condition	Va	lue	Unit	
Falameter	Symbol	Fininanie	Condition	Min	Max	01111	
Serial clock cycle time	tscyc	SCK		5 tмськ* ³	—	ns	
$SCK^{\uparrow} o SOT$ delay time	tsнovi	SCK, SOT	Internal clock	-50	+50	ns	
Valid SIN $ ightarrow$ SCK \downarrow	tı∨s⊔	SCK, SIN	operation output pin: C∟ = 80 pF + 1 TTL	tмськ*3 + 80	—	ns	
$SCK{ ightarrow}{ ightarrow}$ valid SIN hold time	tslixi	SCK, SIN		0	—	ns	
Serial clock "H" pulse width	t shsl	SCK		3 tMCLK ^{*3} – tR	—	ns	
Serial clock "L" pulse width	t slsh	SCK		tмськ*3 + 10	—	ns	
$SCK^{\uparrow} o SOT$ delay time	t SHOVE	SCK, SOT	External clock	—	2 tмськ*3 + 60	ns	
Valid SIN $ ightarrow$ SCK \downarrow	tivsle	SCK, SIN	operation output pin:	30	—	ns	
$SCK \!$	t SLIXE	SCK, SIN	C∟ = 80 pF + 1 TTL	tмськ*3 + 30	—	ns	
SCK falling time	t⊧	SCK		—	10	ns	
SCK rising time	tR	SCK		_	10	ns	

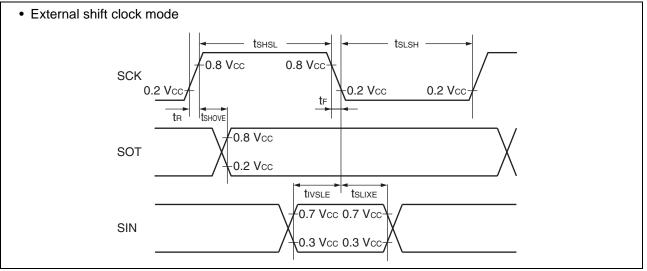
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock/Machine Clock" for tMCLK.









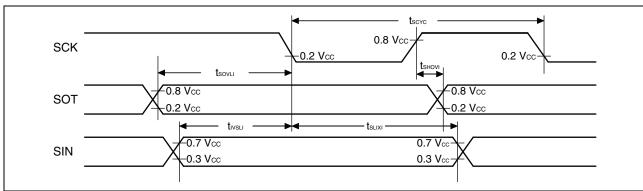
Sampling is executed at the rising edge of the sampling clock^{*1}, and serial clock delay is enabled^{*2}. (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

				Va	lue	
Parameter	Symbol	Pin name	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 tмськ* ³	—	ns
$SCK^{\uparrow} \to SOT$ delay time	tsнovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsli	SCK, SIN	operation output pin:	tмськ*3 + 80		ns
$SCK \!$	tslixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns
$SOT o SCK \downarrow$ delay time	tsovli	SCK, SOT	1	3tмськ*3 – 70	—	ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock/Machine Clock" for tMCLK.



Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

(Vcc = 5.0 V±10%, Vss = 0.0 V, T_A = -40°C to +85°C)

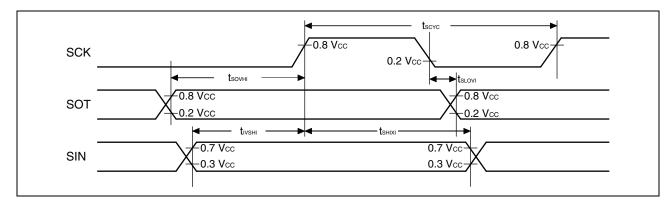
Parameter	Symbol	Pin name	Condition	Va	Unit		
Farameter	Symbol	Fin name	Condition	Min	Max	Unit	
Serial clock cycle time	tscyc	SCK		5 tmclk*3	—	ns	
$SCK\!\!\downarrow ightarrowSOT$ delay time	tslovi	SCK, SOT	Internal clock	-50	+50	ns	
Valid SIN $ ightarrow$ SCK \uparrow	t ivshi		operation output pin:	tmclk*3 + 80	_	ns	
$SCK^{\uparrow} \rightarrow valid SIN hold time$	tshixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns	
$SOT o SCK^{\uparrow}delay$ time	tsovнi	SCK, SOT		$3t$ MCLK $^{*3}-70$	_	ns	

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock/Machine Clock" for tMCLK.





18.4.7 Low-voltage Detection

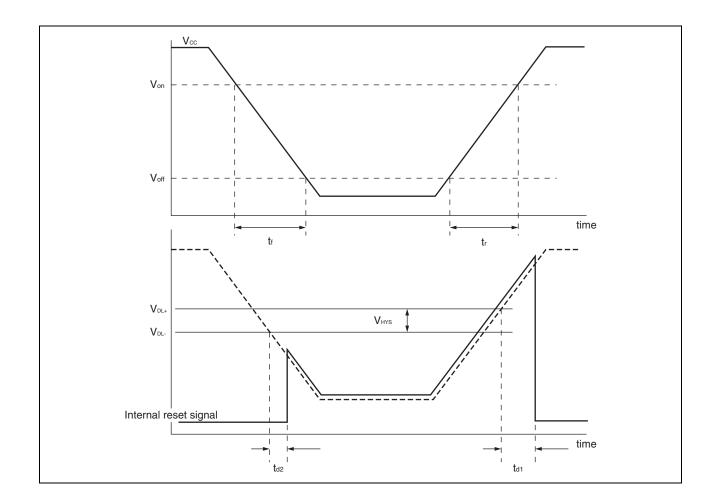
(Vss = 0.0 V, TA = $-40^{\circ}C$ to $+85^{\circ}C$)

Parameter	Symbol		Value		Unit	Remarks			
Parameter	Symbol	Min	Тур	Max	Unit	Remarks			
		2.52	2.7	2.88					
Release voltage*	Vdl+	2.61	2.8	2.99	V	At power supply rise			
Release vollage	V DL+	2.89	3.1	3.31		At power supply lise			
		3.08	3.3	3.52					
		2.43	2.6	2.77					
Detection voltage*	Vdl-	2.52	2.7	2.88	V	At power supply fall			
Delection voltage	V DL-	2.80	3	3.20		At power supply fail			
		2.99	3.2	3.41					
Hysteresis width	VHYS	—	_	100	mV				
Power supply start voltage	Voff		_	2.3	V				
Power supply end voltage	Von	4.9	_	—	V				
Power supply voltage change time (at power supply rise)	tr	650	_	_	μs	Slope of power supply that the reset release signal generates within the rating (V _{DL+})			
Power supply voltage change time (at power supply fall)	tr	650			μs	Slope of power supply that the reset detection signal generates within the rating (V _{DL} -)			
Reset release delay time	t _{d1}		—	30	μs				
Reset detection delay time	t _{d2}	_	_	30	μs				
LVD reset threshold voltage transition stabilization time	tstb	10		_	μs				

*: The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to "CHAPTER 16 LOW-VOLTAGE DETECTION RESET CIRCUIT" in "New 8FX MB95630H Series Hardware Manual".









18.4.8 PC Bus Interface Timing

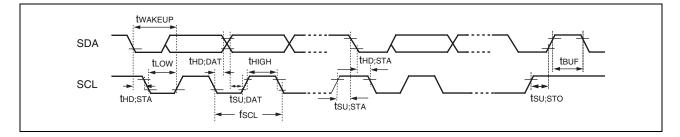
					Va	lue		
Parameter	Symbol	Pin name	Condition	Standard- mode		Fast-mode		Unit
				Min	Max	Min	Max	
SCL clock frequency	fsc∟	SCL		0	100	0	400	kHz
(Repeated) START condition hold time SDA $\downarrow \rightarrow$ SCL \downarrow	thd;sta	SCL, SDA		4.0	_	0.6	_	μs
SCL clock "L" width	tLOW	SCL		4.7	—	1.3		μs
SCL clock "H" width	tніgн	SCL		4.0	_	0.6		μs
(Repeated) START condition setup time SCL $\uparrow \rightarrow$ SDA \downarrow	tsu;sta	SCL, SDA	R = 1.7 kΩ, C = 50 pF*1	4.7	_	0.6	_	μs
Data hold time $SCL \downarrow \rightarrow SDA \downarrow \uparrow$	t hd;dat	SCL, SDA	0 - 00 pi	0	3.45 ^{*2}	0	0.9 ^{*3}	μs
Data setup time SDA $\downarrow \uparrow \rightarrow$ SCL \uparrow	tsu;dat	SCL, SDA		0.25	_	0.1	_	μs
STOP condition setup time SCL $\uparrow \rightarrow$ SDA \uparrow	tsu;sто	SCL, SDA		4	_	0.6	_	μs
Bus free time between STOP condition and START condition	t BUF	SCL, SDA		4.7	_	1.3	_	μs

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

*1: R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

*2: The maximum tho;DAT in the Standard-mode is applicable only when the time during which the device is holding the SCL signal at "L" (tLow) does not extend.

*3: A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, provided that the condition of tsu;DAT ≥ 250 ns is fulfilled.





		Pin		Valı	$(VCC = 5.0 V \pm 10\%, V)$													
Parameter	Symbol	name	Condition	Min	Max	Unit	Remarks											
SCL clock "L" width	t∟ow	SCL		(2 + nm/2)tмськ – 20	_	ns	Master mode											
SCL clock "H" width	t high	SCL		(nm/2)tмськ – 20	(nm/2)tмськ + 20	ns	Master mode											
START condition hold time	thd;sta	SCL, SDA		(-1 + nm/2)tмськ – 20	(-1 + nm)tmclk + 20	ns	Master mode Maximum value is applied when m, n = 1, 8. Otherwise, the minimum value is applied.											
STOP condition setup time	t su;sто	SCL, SDA													(1 + nm/2)tмськ – 20	(1 + nm/2)tмськ + 20	ns	Master mode
START condition setup time	t su;sta	SCL, SDA		(1 + nm/2)tмськ – 20	(1 + nm/2)tмськ + 20	ns	Master mode											
Bus free time between STOP condition and START condition	tbur	SCL, SDA	D 4710	(2 nm + 4) tмськ – 20	_	ns												
Data hold time	t hd;dat	SCL, SDA	R = 1.7 kΩ, C = 50 pF ^{*1}	3 tмськ – 20	_	ns	Master mode											
Data setup time	tsu;dat	SCL, SDA		(-2 + nm/2) tмс∟к – 20	(-1 + nm/2) tмс∟к + 20	ns	Master mode It is assumed that "L" of SCL is not extended. The minimum value is applied to the first bit of continuous data. Otherwise, the maximum value is applied.											
Setup time between clearing interrupt and SCL rising	tsu;int	SCL		(nm/2) tмс∟к – 20	(1 + nm/2) tмськ + 20	ns	The minimum value is applied to the interrupt at the ninth SCL↓. The maximum value is applied to the interrupt at the eighth SCL↓.											
SCL clock "L" width	t∟ow	SCL		4 tmclk – 20	_	ns	At reception											
SCL clock "H" width	tніgн	SCL		4 tmclk – 20	_	ns	At reception											

(Vcc = 5.0 V±10%, Vss = 0.0 V, T_A = -40°C to +85°C)



(Continued)

Parameter	Symbol	Pin	Condition	Value* ²		Unit																							
Parameter	Symbol	name	Condition	Min	Max	Unit																							
START condition detection	thd;sta	SCL, SDA		2 tмс∟к – 20	_	ns	No START condition is detected when 1 tмс∟к is used at reception.																						
STOP condition detection	tsu;sto	SCL, SDA	R = 1.7 kΩ, -C = 50 pF*1	2 тмськ – 20	_	ns	No STOP condition is detected when 1 tмc∟κ is used at reception.																						
RESTART condition detection condition	tsu;sta	SCL, SDA		2 tмс∟к – 20	_	ns	No RESTART condition is detected when 1 tмс∟к is used at reception.																						
Bus free time	t BUF	SCL, SDA			2 tmclk – 20	_	ns	At reception																					
Data hold time	t hd;dat	SCL, SDA]														_					_	2 tmclk – 20	_	ns
Data setup time	tsu;dat	SCL, SDA		$t_{\text{LOW}} - 3 t_{\text{MCLK}} - 20$	_	ns	At slave transmission mode																						
Data hold time	t hd;dat	SCL, SDA		0	_	ns	At reception																						
Data setup time	tsu;dat	SCL, SDA		tмськ – 20	_	ns	At reception																						
SDA↓ → SCL↑ (with wakeup function in use)	t wakeup	SCL, SDA		Oscillation stabilization wait time +2 tMCLK - 20		ns																							

(Vcc = 5.0 V±10%, Vss = 0.0 V, T_A = -40°C to +85°C)

*1: R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

*2: • See "Source Clock/Machine Clock" for tMCLK.

• m represents the CS[4:3] bits in the I²C clock control register ch. 0 (ICCR0).

• n represents the CS[2:0] bits in the I²C clock control register ch. 0 (ICCR0).

- The actual timing of the I²C bus interface is determined by the values of m and n set by the machine clock (tMCLK) and the CS[4:0] bits in the ICCR0 register.
- Standard-mode:

m and n can be set to values in the following range: $0.9 \text{ MHz} < t_{MCLK}$ (machine clock) < 16.25 MHz. The usable frequencies of the machine clock are determined by the settings of m and n as shown below.

	(m, n) = (1, 8)	: 0.9 MHz < tmclk \leq 1 MHz
	(m, n) = (1, 22), (5, 4), (6, 4), (7, 4), (8, 4)	: 0.9 MHz < tmclk \leq 2 MHz
	(m, n) = (1, 38), (5, 8), (6, 8), (7, 8), (8, 8)	: 0.9 MHz < tmclk \leq 4 MHz
	(m, n) = (1, 98), (5, 22), (6, 22), (7, 22)	: 0.9 MHz < tmclk \leq 10 MHz
	(m, n) = (8, 22)	: 0.9 MHz < tмс∟к ≤ 16.25 MHz
•	Fast-mode:	
	m and n can be set to values in the following	range: 3.3 MHz < tMCLK (machine clock) < 16.25 MHz.
	The usable frequencies of the machine clock	are determined by the settings of m and n as shown below.
	(m, n) = (1, 8)	: 3.3 MHz < tmclk \leq 4 MHz
	(m, n) = (1, 22), (5, 4)	: 3.3 MHz < tmclk \leq 8 MHz
	(m, n) = (1, 38), (6, 4), (7, 4), (8, 4)	: 3.3 MHz < tмс∟к ≤ 10 MHz

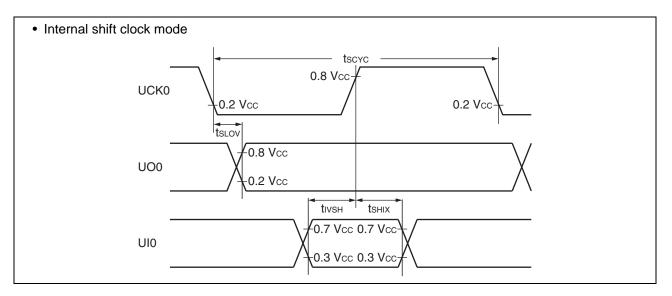
 $(m, n) = (5, 8) \qquad (5, 4), (7, 4), (6, 4) \qquad (5, 3) \qquad (5, 3) \qquad (5, 3) \qquad (6, 4) \qquad (7, 4), (6, 4) \qquad (7, 4), (6, 4) \qquad (7, 4), (7,$



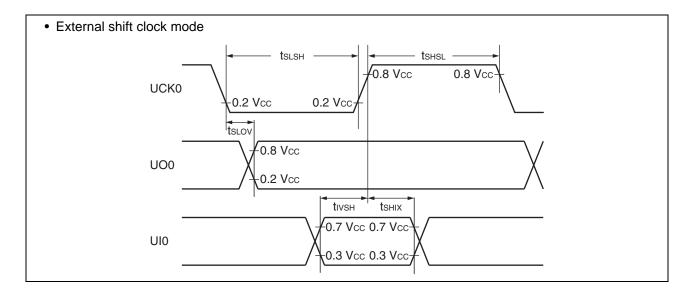
18.4.9 UART/SIO, Serial I/O Timing

,	0		(Vcc = 5.0 V±10%	∕₀, Vss = 0.	0 V, TA =	–40°C
Parameter	Symbol	Pin name	Condition	Va	ue	Unit
Farameter	Symbol	Fin name	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	UCK0		4 t мськ*	_	ns
UCK $\downarrow \rightarrow$ UO time	t slov	UCK0, UO0	Internal clock operation	-190	+190	ns
Valid UI \rightarrow UCK \uparrow	tıvsн	UCK0, UI0		2 tmclk*	_	ns
UCK $\uparrow \rightarrow$ valid UI hold time	tsнix	UCK0, UI0		2 tmclk*	_	ns
Serial clock "H" pulse width	tsнs∟	UCK0		4 t мськ*	_	ns
Serial clock "L" pulse width	tslsh	UCK0		4 t мськ*	_	ns
UCK $\downarrow \rightarrow$ UO time	tslov	UCK0, UO0	External clock operation	—	190	ns
Valid UI \rightarrow UCK \uparrow	tıvsн	UCK0, UI0		2 t мськ*	_	ns
UCK $\uparrow \rightarrow$ valid UI hold time	tsнix	UCK0, UI0]	2 tmclk*		ns

*: See "Source Clock/Machine Clock" for tMCLK.



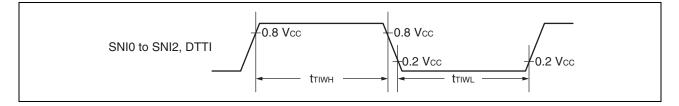




18.4.10 MPG Input Timing

 $(Vcc = 5.0 V \pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
i arameter	Symbol	i in name	Condition	Min	Max	Unit	Neillai KS
Input pulse width	tтıwн, t⊤ıw∟	SNI0 to SNI2, DTTI	—	4 tmclk	_	ns	



18.4.11 Comparator Timing

 $(Vcc = 2.4 V \text{ to } 5.5 V, Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Parameter	Pin name		Value		Unit	Remarks
Farameter		Min	Тур	Max	Unit	i cilial ka
Voltage range	CMP0_P, CMP0_N	0	_	Vcc - 1.3	V	
Offset voltage	CMP0_P, CMP0_N	-15	_	+15	mV	
Delay time	CMP0 O	_	650	1200	ns	Overdrive 5 mV
Delay line		_	140	420	ns	Overdrive 50 mV
Power down delay	CMP0_O	_	_	1200	ns	Power down recovery PD: $1 \rightarrow 0$
Power up stabilization time	CMP0_O		_	1200	ns	Output stabilization time at power up



18.5 A/D Converter

18.5.1 A/D Converter Electrical Characteristics

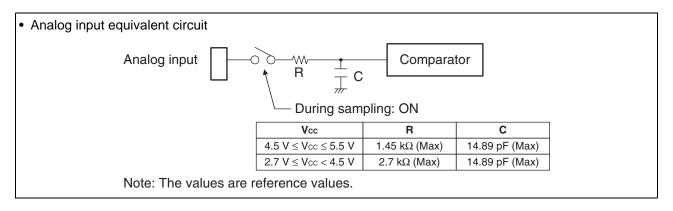
$(Vcc = 2.7 V \text{ to } 5.5 V, Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Parameter	Symbol	Value				Remarks	
T arameter	Symbol	Min	Min Typ		Unit	Kemarko	
Resolution		—	—	10	bit		
Total error		-3		+3	LSB		
Linearity error		-2.5		+2.5	LSB		
Differential linearity error		-1.9	—	+1.9	LSB		
Zero transition voltage	Vот	Vss – 1.5 LSB	Vss + 0.5 LSB	Vss + 2.5 LSB	V		
Full-scale transition voltage	Vfst	Vcc – 4.5 LSB	Vcc – 2 LSB	Vcc + 0.5 LSB	V		
Compare time	—	3	—	10	μs	$2.7~\text{V} \leq \text{Vcc} \leq 5.5~\text{V}$	
Sampling time	_	0.941	_	œ	μs	$2.7 V \le V_{CC} \le 5.5 V$, with external impedance < $3.3 k\Omega$ and external capacitance = 10 pF	
Analog input current	Iain	-0.3	—	+0.3	μA		
Analog input voltage	VAIN	Vss	—	Vcc	V		

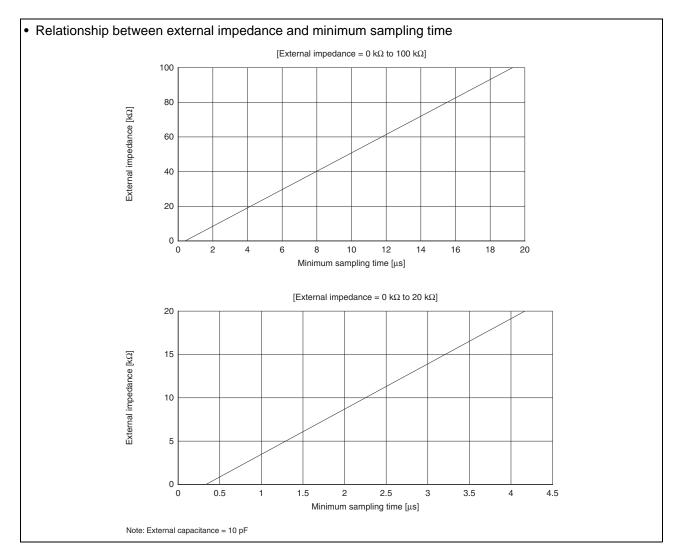
18.5.2 Notes on Using A/D Converter

• External impedance of analog input and its sampling time

The A/D converter of the MB95630H Series has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 μ F to the analog input pin.







• A/D conversion error

As |Vcc - Vss| decreases, the A/D conversion error increases proportionately.



18.5.3 Definitions of A/D Converter Terms

Resolution

٠

It indicates the level of analog variation that can be distinguished by the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

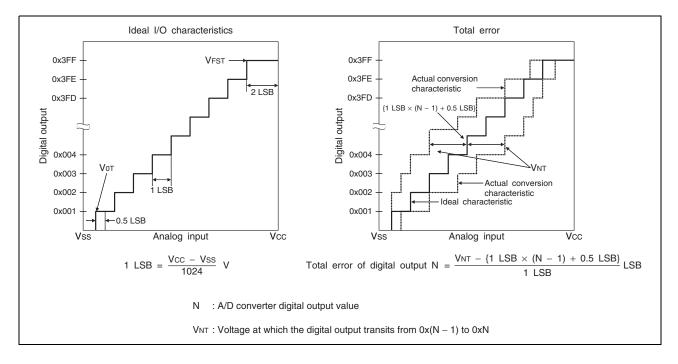
• Linearity error (unit: LSB)

It indicates how much an actual conversion value deviates from the straight line connecting the zero transition point ("000000000" $\leftarrow \rightarrow$ "0000000001") of a device to the full-scale transition point ("1111111111" $\leftarrow \rightarrow$ "111111110") of the same device.

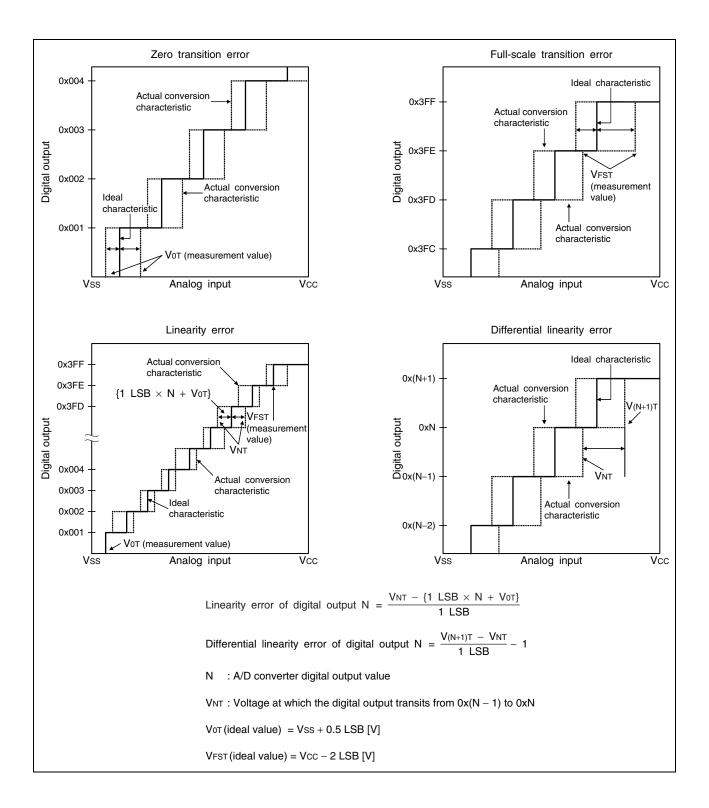
• Differential linear error (unit: LSB)

It indicates how much the input voltage required to change the output code by 1 LSB deviates from an ideal value. Total error (unit: LSB)

It indicates the difference between an actual value and a theoretical value. The error can be caused by a zero transition error, a full-scale transition errors, a linearity error, a quantum error, or noise.









18.6 Flash Memory Program/Erase Characteristics

Parameter		Value		Unit	Remarks
Farameter	Min	Тур	Max	Unit	Remarks
Sector erase time (2 Kbyte sector)	_	0.3* ¹	1.6* ²	s	The time of writing "0x00" prior to erasure is excluded.
Sector erase time (32 Kbyte sector)	_	0.6* ¹	3.1* ²	s	The time of writing "0x00" prior to erasure is excluded.
Byte writing time	—	17	272	μs	System-level overhead is excluded.
Program/erase cycle	100000		_	cycle	
Power supply voltage at program/erase	2.4		5.5	V	
	20* ³	_	_		Average T _A = +85°C Number of program/erase cycles: 1000 or below
Flash memory data retention time	10* ³	_	_	year	Average $T_A = +85^{\circ}C$ Number of program/erase cycles: 1001 to 10000 inclusive
	5* ³		_		Average T _A = +85°C Number of program/erase cycles: 10001 or above

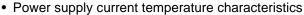
*1: Vcc = 5.5 V, TA = +25°C, 0 cycle

*2: Vcc = 2.4 V, T_A = +85°C, 100000 cycles

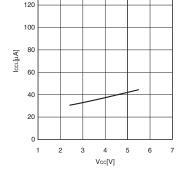
*3: These values were converted from the result of a technology reliability assessment. (These values were converted from the result of a high temperature accelerated test using the Arrhenius equation with the average temperature being +85°C.)

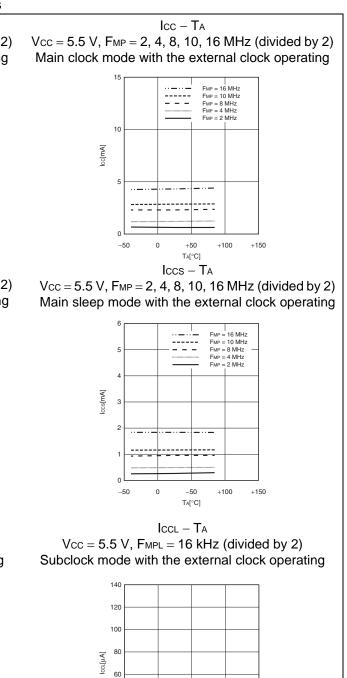


19. Sample Characteristics



Icc – Vcc $T_A = +25^{\circ}C$, $F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main clock mode with the external clock operating 15 FMP = 16 MHz FMP = 10 MHz FMP = 8 MHz FMP = 4 MHz FMP = 2 MHz ----10 lcc[mA] 5 0 2 5 7 3 6 1 4 Vcc[V] Iccs – Vcc $T_A = +25^{\circ}C$, $F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main sleep mode with the external clock operating · _ · · _ FMP = 16 MHz FMP = 10 MHz FMP = 8 MHz ____ 5 FMP = 4 MHz $F_{MP} = 2 MH_2$ locs[mA] 2 ----_ _ 0 1 2 3 4 5 6 7 Vcc[V] $\mathsf{ICCL} - \mathsf{VCC}$ $T_A = +25^{\circ}C$, $F_{MPL} = 16 \text{ kHz}$ (divided by 2) Subclock mode with the external clock operating 140 120





40

20

0

-50

0

+50

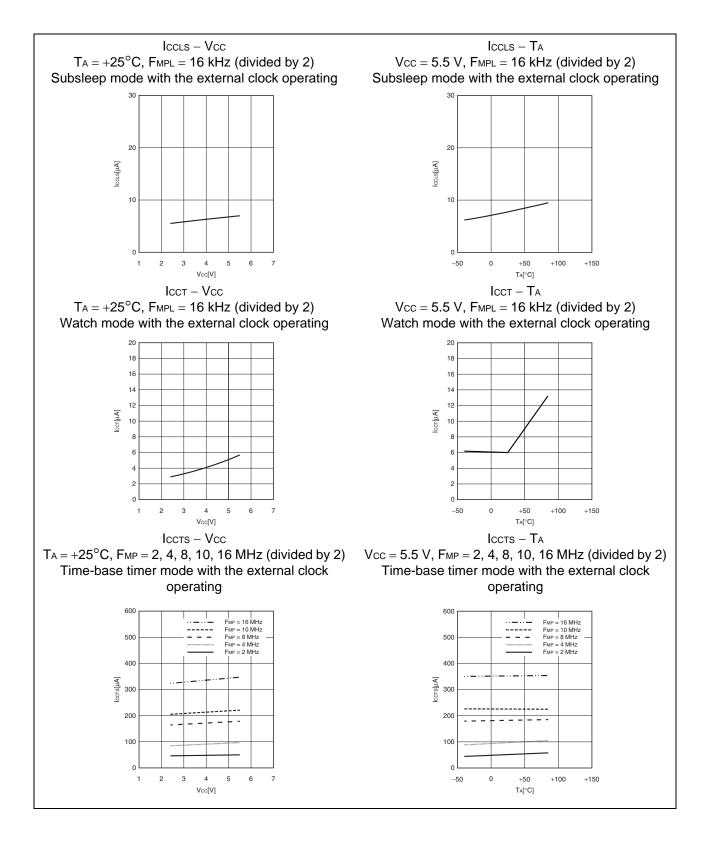
T_A[°C]

+100

+150

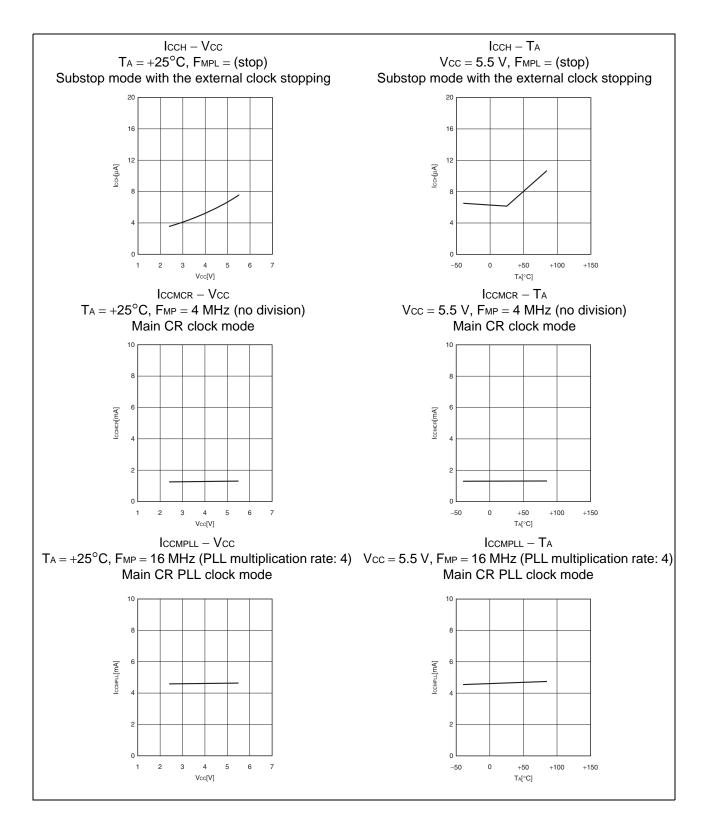




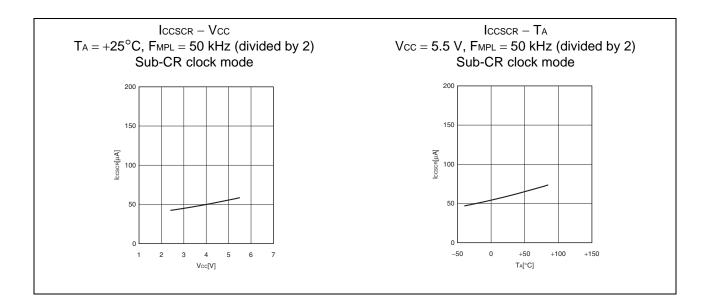






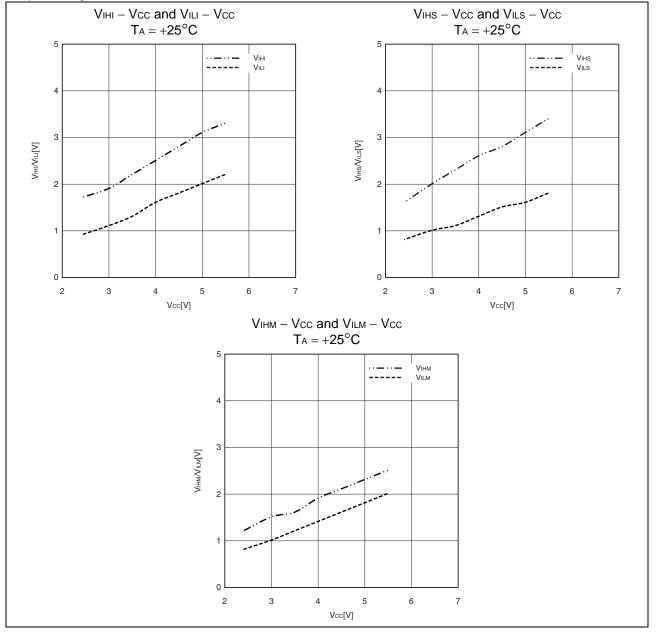






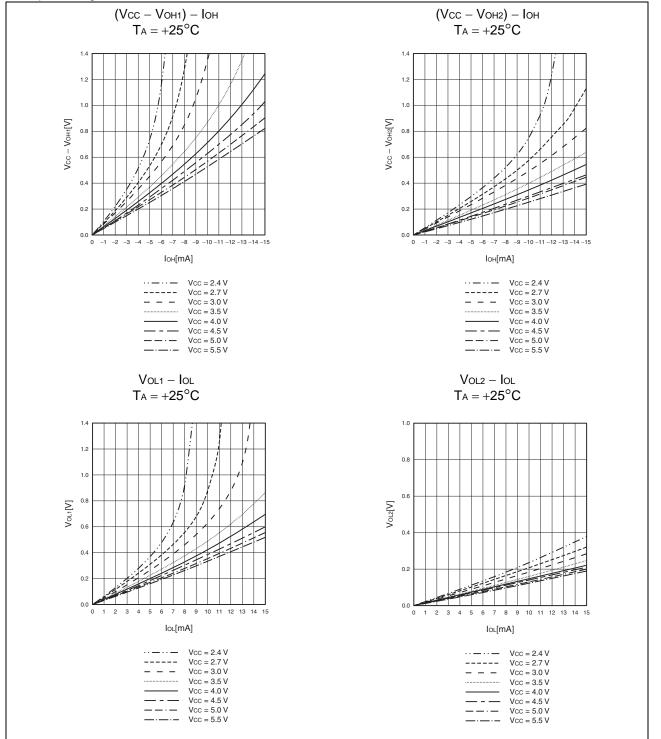


• Input voltage characteristics



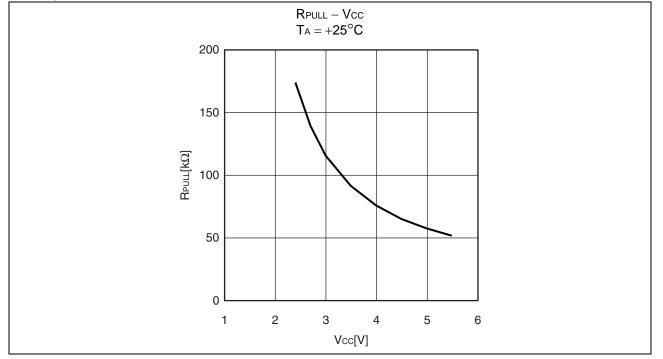


• Output voltage characteristics





• Pull-up characteristics





20. Mask Options

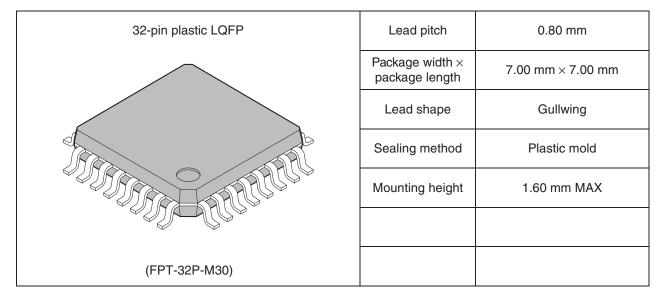
No.	Part number	MB95F632H MB95F633H MB95F634H MB95F636H	MB95F632K MB95F633K MB95F634K MB95F636K		
	Selectable/Fixed	Fixed			
1	Low-voltage detection reset	Without low-voltage detection reset	With low-voltage detection reset		
2	Reset	With dedicated reset input	Without dedicated reset input		

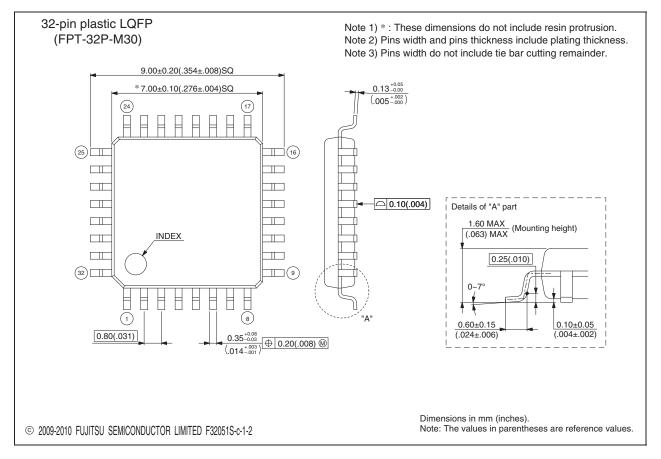
21. Ordering Information

Part number	Package
MB95F632HPMC-G-SNE2 MB95F632KPMC-G-SNE2 MB95F633HPMC-G-SNE2 MB95F633KPMC-G-SNE2 MB95F634HPMC-G-SNE2 MB95F636HPMC-G-SNE2 MB95F636KPMC-G-SNE2 MB95F636KPMC-G-UNE2	32-pin plastic LQFP (FPT-32P-M30)
MB95F632HP-G-SH-SNE2 MB95F632KP-G-SH-SNE2 MB95F633HP-G-SH-SNE2 MB95F633KP-G-SH-SNE2 MB95F634HP-G-SH-SNE2 MB95F634KP-G-SH-SNE2 MB95F636HP-G-SH-SNE2 MB95F636KP-G-SH-SNE2	32-pin plastic SH-DIP (DIP-32P-M06)
MB95F632HWQN-G-SNE1 MB95F632KWQN-G-SNE1 MB95F633HWQN-G-SNE1 MB95F633KWQN-G-SNE1 MB95F634HWQN-G-SNE1 MB95F634KWQN-G-SNE1 MB95F636HWQN-G-SNE1	32-pin plastic QFN (LCC-32P-M19)



22. Package Dimension

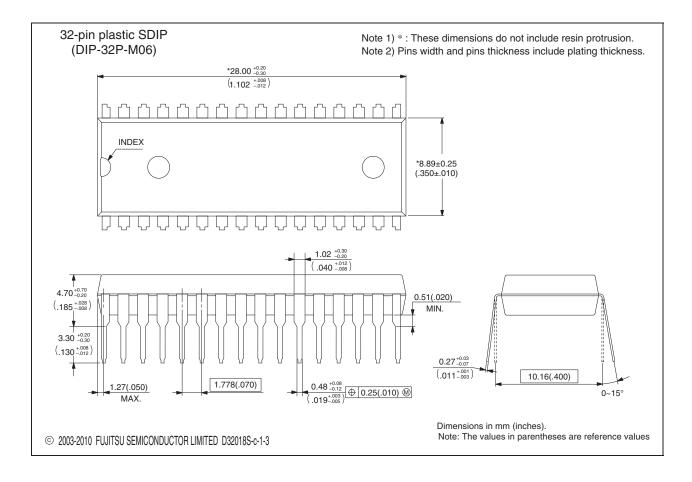






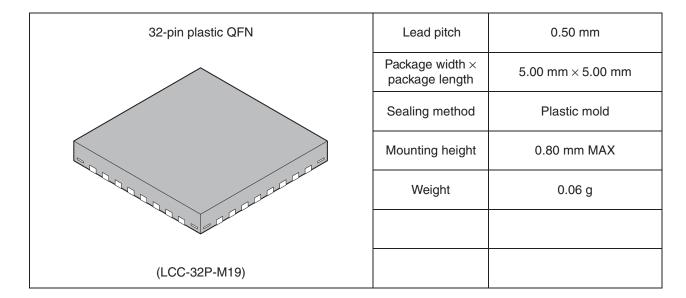


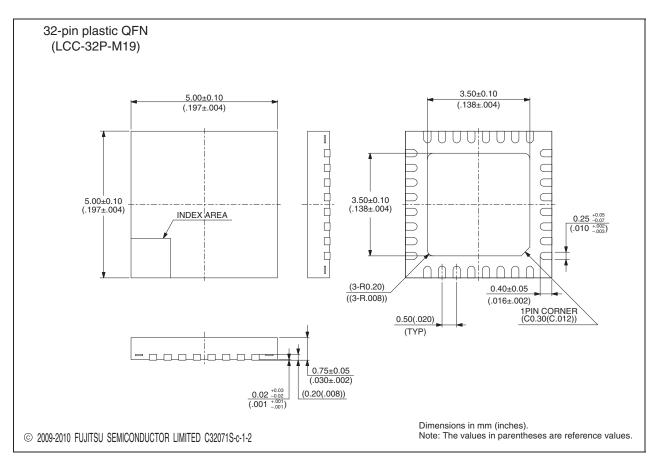
32-pin plastic SDIP	Lead pitch	1.778 mm
	Low space	10.16 mm
TH	Sealing method	Plastic mold
(DIP-32P-M06)		















23. Major Changes In This Edition

Spansion Publication Number: DS702-00009-3v0-E

Page	Section	Details
22	 PIN CONNECTION C pin 	Corrected the following statement. The bypass capacitor for the Vcc pin must have a capacitance larger than Cs. → The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs.
66	 ELECTRICAL CHARACTERISTICS Recommended Operating Conditions 	Corrected the following statement in remark *2. The bypass capacitor for the Vcc pin must have a capacitance larger than Cs. \rightarrow The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs.
71	4. AC Characteristics(1) Clock Timing	Corrected the pin names of the parameter "Input clock rising time and falling time". X0 \rightarrow X0, X0A X0, X1 \rightarrow X0, X1, X0A, X1A

NOTE: Please see "Document History" about later revised information.

Document History Page

	Document Title: MB95630H Series, New 8FX 8-bit Microcontrollers Document Number: 002-04627					
Revision	ECN	Orig. of Change	Submission Date	Description of Change		
**	-	AKIH	06/07/2013	Migrated to Cypress and assigned document number 002-04627. No change to document contents or format.		
*A	5193921	AKIH	03/29/2016	Updated to Cypress template Added "MB95F636KPMC-G-UNE2" in "Ordering Information"		



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